

MILITARY SPECIFICATION

MICROCIRCUITS, DIGITAL, HIGH SPEED, CMOS,
FLIP-FLOPS MONOLITHIC SILICON

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE

1.1 Scope. This specification covers the detail requirements for monolithic silicon, high speed, CMOS, logic microcircuits. Two product assurance classes and a choice of case outlines and lead finishes are provided and are reflected in the complete part number.

1.2 Part number. The part number shall be in accordance with MIL-M-38510, and as specified herein.

1.2.1 Device type. The device types shall be as follows:

<u>Device type</u>	<u>Circuit</u>
01	Octal D - Flip-Flop with Clear
02	Octal Three-State D Flip-Flop
03	Octal D - Flip-Flop with Enable
04	Octal Three-State D Flip-Flop
05	Octal Three-State D Flip-Flop w/inverting outputs
06	Octal Three-State D Flip-Flop w/inverting outputs
52	Octal Three-State D Flip-Flop (LS-TTL input)

1.2.2 Device class. The device class shall be the product assurance level as defined in MIL-M-38510.

1.2.3 Case outlines. The case outlines shall be designated as follows:

<u>Outline letter</u>	<u>Case outline (see MIL-M-38510, appendix C)</u>
8	D-8 (20-lead, 1/4" x 1-1/6"), dual-in-line package
2	C-2 (20-terminal, .350" x .350") square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage (V_{CC})	- - - - -	-0.5 V dc +7.0 V dc
DC input voltage (V_I)	- - - - -	-0.5 V dc to V_{CC} +0.5 V dc
DC output voltage (V_{OUT})	- - - - -	-0.5 V dc to V_{CC} +0.5 V dc
Clamp diode current (I_{IK} , I_{OK})	- - - - -	*20 mA
DC output current per pin (I_{OUT})	- - - - -	*25 mA
DC V_{CC} or GND current per pin (I_{OC})	- - - - -	*50 mA
Storage temperature range (T_{STG})	- - - - -	-65°C to +150°C
Maximum power dissipation (P_D)	- - - - -	300 mW (02, 04-06, 52, 420 mW)
Lead temperature (soldering, 10 seconds)	- - - - -	+300°C
Thermal resistance, junction-to-case (θ_{JC}):		
Case R	- - - - -	(See MIL-M-38510, appendix C)
Case 2	- - - - -	60°C/W
Junction temperature (T_J)	- - - - -	+175°C

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to: Rome Air Development Center (RBE-2), Griffiss AFB, NY 13441, by using the self-addressed Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or by letter.

1.4 Recommended operating conditions.

Device types 01, 02, 03, 04, 05, 06:

Input low (V_{IL}) maximum voltage - - - - -	0.3 V at V_{CC} = 2 V 0.9 V at V_{CC} = 4.5 V 1.2 V at V_{CC} = 6 V
Input high (V_{IH}) minimum voltage- - - - -	1.5 V at V_{CC} = 3 V 3.15 V at V_{CC} = 4.5 V 4.2 V at V_{CC} = 6 V

Device types 01, 02, 03, 04, 05, 06:

Supply voltage (V_{CC}) - - - - -	2 V dc minimum to 6 V dc maximum
Output voltage - - - - -	0 V dc to V_{CC}
Operating temperature- - - - -	-55°C to +125°C

Input rise and fall times (t_r, t_f) maximum:

$V_{CC} = 2$ V	1000 ns
$V_{CC} = 4.5$ V	500 ns
$V_{CC} = 6$ V	400 ns

Device type 52:

Input low (V_{IL}) maximum voltage- - - - -	0.8 at V_{CC} = 4.5 to 5.5
Input high (V_{IH}) minimum voltage - - - - -	2.0 V at V_{CC} = 4.5 - 5.5
Supply voltage (V_{CC}) - - - - -	4.5 V to 5.5 V dc
Output voltage - - - - -	0 V dc to 5.5 V dc
Operating temperature- - - - -	-55°C to +125°C

Input rise and fall times (t_r, t_f):

$V_{CC} = 4.5$ V	500 ns
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Setup time before clock (t_{SU}) 20 ns minimum.Hold time (t_H):

Device types 01, 03, 04, 06 - - - - -	5 ns minimum
Device types 02, 05, 52 - - - - -	10 ns minimum

Clock pulse (t_{CLK}):

Device types 02, 04, 05, 06 - - - - -	16 ns minimum
Device type 01 - - - - -	18 ns minimum
Device types 03, 52 - - - - -	20 ns minimum

(t_{REM}):

Device type 01- - - - -	20 ns minimum
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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this specification to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this specification and the references cited herein (except for associated detail specifications, specification sheets or MS standards), the text of this specification shall take precedence. Nothing in this specification, however, shall supersede applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Detail specification. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Logic diagram and terminal connections. The logic diagram and terminal connections shall be as specified on figure 1.

3.2.2 Truth tables. The truth tables shall be as specified on figure 2.

3.2.3 Schematic circuits. The schematic circuits shall be submitted to the preparing activity prior to inclusion of a manufacturer's device in this specification and shall be submitted to the qualifying activity as a prerequisite for qualification. All qualified manufacturers' schematics shall be maintained and available upon request.

3.2.4 Case outlines. The case outlines shall be as specified in 1.2.3.

3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510 and 6.4 herein.

3.4 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I, and apply over the full recommended ambient operating temperature range.

3.5 Electrical test requirements. The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.

3.6 Marking. Marking shall be in accordance with MIL-M-38510. At the option of the manufacturer, marking of the country of origin may be omitted from the body of the microcircuit, but shall be retained on the initial container.

3.6.1. Total dose radiation hardness identifier. Total dose radiation hardness identifier shall be in accordance with MIL-M-38510 and 4.5.4 herein.

3.6.2 Serialization. All class S devices shall be serialized in accordance with MIL-M-38510.

3.6.3 Correctness of indexing and marking. All devices shall be subjected to the final electrical tests specified in table II after part number marking to verify that they are correctly indexed and identified by part number. Optionally, an approved electrical test may be devised especially for this requirement.

3.7 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit group number 38 (see MIL-M-38510, appendix E).

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and methods 5005 and 5007, as applicable, of MIL-STD-883, except as modified herein.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to qualification and quality conformance inspection. The following additional criteria shall apply:

- a. Delete the sequence specified in 3.1.10 through 3.1.14 of method 5004 and substitute lines 1 through 7 of table II herein.
- b. Burn-in (method 1015 of MIL-STD-883).
 - (1) Static test (test condition A) using circuit shown on figure 3, or equivalent. Ambient temperature (T_A) shall be $+125^{\circ}\text{C}$ minimum. Test duration for each static test shall be 24 hours minimum for class S devices and in accordance with table I of method 1015 for class B devices.
 - (2) Dynamic test (test condition D) using circuit shown on figure 3, or equivalent. Ambient temperature shall be $+125^{\circ}\text{C}$ minimum. Test duration shall be in accordance with table I of method 1015.
- c. Interim and final electrical parameters shall be as specified in table II herein.
- d. For class S devices, post dynamic burn-in, or class B devices, post static burn-in, electrical parameter measurements may, at the manufacturer's option, be performed separately or included in the final electrical parameter requirements.

4.2.1 Percent defective allowable (PDA).

- a. The PDA for class S devices shall be 5 percent for static burn-in and 5 percent for dynamic burn-in, based on the exact number of devices submitted to each separate burn-in.
- b. Static burn-in I and II failures shall be cumulative for determining the PDA.
- c. The PDA for class B devices shall be in accordance with MIL-M-38510 for static burn-in. Dynamic burn-in is not required.
- d. Those devices whose measured characteristics, after burn-in, exceed the specified delta (Δ) limits or electrical parameter limits specified in table III, subgroup 1, are defective and shall be removed from the lot. The verified failures divided by the total number of devices in the lot initially submitted to burn-in shall be used to determine the percent defective for the lot and the lot shall be accepted or rejected based on the specified PDA.

4.3 Qualification inspection. Qualification inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5).

4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510 and as specified herein. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5).

4.4.1 Group A inspection. Group A inspection shall be in accordance with table I of method 5005 of MIL-STD-883 and as follows:

- a. Tests shall be performed in accordance with table II herein.
- b. Subgroups 5, 6, 7, and 8 of table I of method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C_i measurement) shall be measured only for initial qualification and after process or design changes which may affect input capacitance. Capacitance shall be measured between the designated terminal and V_{SS} at a frequency of 1 MHz.
- d. Subgroups 9 and 11 shall be measured only for initial qualification and after process or design changes which may affect dynamic performance.

4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of method 5005 of MIL-STD-883 and as follows:

- a. Class S steady-state life (accelerated) test circuits shall be submitted to the qualifying activity for approval. When the alternate steady-state life test is used, the circuit on figure 4, or equivalent, shall be used.
- b. Electrostatic Discharge Sensitivity (ESDS) testing shall be performed in accordance with MIL-STD-883, method 3015. The option to categorize devices as ESD sensitive without performing the test is not allowed. Device types categorized as ESD sensitive shall be further tested using method 3015 modified as follows:
 - (1) Table I pin combinations 4 and 5 shall be deleted.
 - (2) The test sequence specified in 3.b shall be repeated an additional four times rather than the two specified.

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified	Device type	V _{CC}	Limits		
					Min	Max	Unit
High-level output voltage	V _{OH1} 2/	V _{IH} = 1.5 V V _{IL} = 0.3 V I _{OH} = -20 μA	01-06	2.0 V	1.90	---	V
	V _{OH2} 2/	V _{IH} = 3.15 V V _{IL} = 0.9 V I _{OH} = -20 μA	01-06	4.5 V	4.40	---	V
	V _{OH3}	V _{IH} = 4.2 V V _{IL} = 1.2 V I _{OH} = -20 μA	01-06	6.0 V	5.90	---	V
	V _{OH4} 2/	V _{IH} = 3.15 V V _{IL} = 0.9 V I _{OH} = -4.0 mA	01-06	4.5 V	3.7	---	V
	V _{OH5}	V _{IH} = 4.2 V V _{IL} = 1.2 V I _{OH} = -5.2 mA	01-06	6.0 V	5.2	---	V
	V _{OH6}	V _{IH} = 2.0 V V _{IL} = 0.8 V I _{OH} = -20 mA	52	4.5 V	4.4	---	V
	V _{OH7}	V _{IH} = 2.0 V V _{IL} = 0.8 V I _{OH} = -6.0 mA	52	5.5 V	3.7	---	V

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions 1/ $-55^{\circ}\text{C} < T_C < +125^{\circ}\text{C}$ unless otherwise specified	Device type	V _{CC}	Limits		
					Min	Max	Unit
Low-level output voltage	V _{OL1} 2/	V _{IH} = 1.5 V V _{IL} = -0.3 V I _{OL} = 20 μA	01-06	2.0 V	---	0.10	V
	V _{OL2} 2/	V _{IH} = 3.15 V V _{IL} = -0.9 V I _{OL} = 20 μA	01-06	4.5 V	---	0.10	V
	V _{OL3}	V _{IH} = 4.2 V V _{IL} = -1.2 V I _{OL} = 20 μA	01-06	6.0 V	---	0.10	V
	V _{OL4} 2/	V _{IH} = 3.15 V V _{IL} = -0.9 V I _{OL} = 4.0 mA	01-06	4.5 V	---	0.4	V
	V _{OL5}	V _{IH} = 4.2 V V _{IL} = -1.2 V I _{OL} = 5.2 mA	01-06	6.0 V	---	0.4	V
	V _{OL6}	V _{IH} = 2.0 V V _{IL} = 0.8 V I _{OL} = 20 mA	52	4.5 V	---	0.1	V
	V _{OL7}	V _{IH} = 2.0 V V _{IL} = 0.8 V I _{OL} = 6.0 mA	52	5.5 V	---	0.4	V
Positive input clamp voltage	V _{IC+}	V _{CC} = GND I _{IN} = 1 mA T _C = +25°C	01-06 52	---	---	1.5	V
Negative input clamp voltage	V _{IC-}	V _{CC} = Open I _{IN} = -1 mA T _C = +25°C	01-06 52	---	---	-1.5	V
Input current low	I _{IL}	V _{IN} = GND	01-06 52	6.0 V 5.5 V	---	-0.1	μA
Input current high	I _{IH}	V _{IN} = V _{CC}	01-06 52	6.0 5.5 V	---	0.1	μA

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions 1/ -55°C < T _C < +125°C unless otherwise specified	Device type	V _{CC}	Limits		Unit
					Min	Max	
Short circuit output current	I _{OS1} 2/	V _O = GND V _I = GND	01,03 02,04, 05,06	2.0 V	-2	-50	mA
	I _{OS2} 2/		01,03 02,04, 05,06	4.5 V	-15	-150	
	I _{OS3} 2/		01,03 02,04, 05,06	6.0 V	-25	-180	
	I _{OS4}		01,03 02,04, 05,06,52	4.0 V	-10	-120	
	I _{OS5} 3/	V _I = 5.5 V	52	5.5 V	-25	-210	V
Supply current quiescent	I _{CC}	V _I = 6.0 V V _I = 5.5 V	01-06 3/	6.0 V 5.5 V	---	8	μA
	I _{CCZ}		02,04, 05,06			4.0	μA
		V _I = 5.5 V	52	5.5 V		4.0	μA
Tri-state output leakage current low	I _{OZL}	V _{OUT} = GND OC = V _{IH} 4/	02,04, 05,06	6.0 V	-0.2 V		μA
Tri-state output leakage current high	I _{OZH}	V _{OUT} = GND OC = V _{IH} 4/	02,04, 05,06	6.0 V	+0.2 V		μA
Input capacitance	C _{IN}	T _C = 25°C	01-06 3/ 52			10	pF
	C _C		01-06, 52			15	pF
Clock, control capacitance tri-state output capacitance	C _O	T _C = 25°C	02,04- 06,52			20	pF
Propagation delay times 5/, 6/ Clear to outputs	t _{PHL1}	C _L = 50 pF ±10%	01	4.5 V		41	ns

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions I/ -55°C ≤ TC ≤ +125°C unless otherwise specified	Device type	V _{CC}	Limits		
					Min	Max	Unit
Propagation delay 5/, 6/ Clock to outputs	t _{PHL2} t _{PLH2}	$C_L = 50 \text{ pF} \pm 10\%$	01	4.5 V		37	ns
			01, 52	4.5 V		42	ns
			03	4.5 V		37	ns
			04	4.5 V		42	ns
			05	4.5 V		42	ns
			06	4.5 V		41	ns
Output enable time 5/, 6/	t _{PZH} t _{PZL}	$C_L = 50 \text{ pF} \pm 10\%$ $R_L = 1 \text{ k}\Omega \pm 10\%$	02	4.5 V		35	ns
			52	4.5 V		41	ns
			04	4.5 V		35	ns
			05	4.5 V		41	ns
			06	4.5 V		35	ns
			02	4.5 V		35	ns
Output disable time 5/, 6/	t _{PHZ} t _{PLZ}	$C_L = 50 \text{ pF} \pm 10\%$ $R_L = 1 \text{ k}\Omega \pm 10\%$	52	4.5 V		41	ns
			04	4.5 V		35	ns
			05	4.5 V		35	ns
			06	4.5 V		35	ns
			02	4.5 V		35	ns
			52	4.5 V		41	ns

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions 1/ $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$ unless otherwise specified	Device type	V _{CC}	Limits		
					Min	Max	Unit
Transition delay 5/, 6/	t_{THL} t_{TLH}	$C_L = 50 \text{ pF} \pm 10\%$	01	4.5 V		20	ns
			02, 52	4.5 V		16	ns
			03	4.5 V		20	ns
			04	4.5 V		16	ns
			05	4.5 V		16	ns
			06	4.5 V		16	ns
Maximum frequency test 5/, 6/	f _{MAX}	$C_L = 50 \text{ pF} \pm 10\%$ 50% duty cycle	01	4.5 V		23	MHz
			02	4.5 V		25	MHz
			52	4.5 V		21	MHz
			03	4.5 V		21	MHz
			04	4.5 V		25	MHz
			05	4.5 V		25	MHz
			06	4.5 V		25	MHz

1/ Complete terminal conditions shall be as specified in table III.

2/ Guaranteed but not tested.

3/ Power dissipation capacitance (C_{PD}) per gate typically equals 25 pF.

4/ I_{OZL} set internal D flip-flops to high state.

I_{OZH} set internal D flip-flops to low state.

5/ Tested at $V_{CC} = 4.5 \text{ V}$ at $+125^{\circ}\text{C}$ for sample testing and $V_{CC} = 4.5 \text{ V}$ at $+25^{\circ}\text{C}$ for screening.
Guaranteed at other V_{CC} voltages and temperatures, see table IA and IB as appropriate and the exception in 4.4.1d.

6/ See the formulae for determining switching times and maximum frequencies shown in tables IA and IB respectively.

TABLE IA. Calculated dynamic figures at -55/25 ambient temperature (°C).

V _{CC}	T _A = (°C)	
	125	-55/25
2.0 V	5.00X	5.00Y
4.5 V	X = 1	0.75X = Y
6.0 V	0.85X	0.85Y

Normalized numbers
(+125°C equals 1)

NOTE: The 2.0 V and 6.0 V numbers are derived from their 4.5 V integer value.
Rounding off according 5/4.

TABLE IB. Calculated f_{MAX} figures at -55/25 ambient temperature (°C).

V _{CC}	T _A = (°C)	
	125	-55/25
2.0 V	0.2X	0.2Y
4.5 V	X = 1	1.33X = Y
6.0 V	1.18X	1.18Y

Normalized numbers
(+125°C equals 1)

NOTE: The 2.0 V and 6.0 V numbers are derived from their 4.5 V integer value.
Rounding off according 5/4.

TABLE II. Burn-in and electrical test requirements.

Line no.	Applicable tests and MIL-STD-883 test method	Class S device 1/				Class B device 1/			
		Ref. para-graph	Table III subgroups 2/	Table IV delta limits 3/	Test circuit figure	Ref. para-graph	Table III subgroups 2/	Table IV delta limits 3/	Test circuit figure
1	Interim electrical parameters (method 5004)		1				1		
2	Static burn-in I (method 1015)	4.2b 4.5.2	Req'd		3		Not req'd		
3	Same as line 1		1	Δ					
4	Static burn-in II (method 1015)	4.2b 4.5.2	Req'd		3	4.2b 4.5.2	4/ Req'd		3
5	Same as line 1	4.2d	1*	Δ		4.2d	1*	Δ	
6	Dynamic burn-in (method 1015)	4.2b 4.5.2	Req'd				Not req'd		
7	Same line 1	4.2d	1	Δ					
8	Final electrical parameters (method 5004)		1*,2,3,9				1*,2,3,9 4/		
9	Group A test requirements (method 5005)	4.4.1	1,2,3,4, 9,10,11			4.4.1	1,2,3,4, 9,10,11		
10	Group B end-point electrical parameters (method 5005)	4.4.2	+1,2,3,9, 10,11	Δ			+1		
11	Group C end-point electrical parameters (method 5005)					4.4.3	1,2	Δ	
12	Group D end-point electrical parameters (method 5005)	4.4.4	1,2,3			4.4.4	1,2		

1/ Blank spaces indicate tests are not applicable.

2/ * indicates PDA applies to subgroup 1 (see 4.2.1).

3/ Δ indicates delta limit shall be required only on table III, subgroup 1, where specified, and the delta values shall be computed with reference to the previous interim electrical parameters (line 1).

4/ The device manufacturer may at his option, either complete subgroup 1 electrical parameter measurements, including delta measurements, within 96 hours after burn-in completion (removal of bias); or may complete subgroup 1 electrical measurements without delta measurements within 24 hours after burn-in completion (removal of bias).

5/ + indicates also applies to electrostatic discharge sensitivity tests.

- (3) Only those device types that pass EDS testing at 1000 volts or greater shall be considered as conforming to the requirements of this specification.
- c. End-point electrical parameters shall be as specified in table II herein. Delta limits shall apply only to subgroup 5 of group B inspections and shall consist of tests specified in table IV herein.

4.4.3 Group C inspection. Group C inspection shall be in accordance with table III of method 5005 of MIL-STD-883 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein. Delta limits shall apply only to subgroup 1 of group C inspection and shall consist of tests specified in table IV herein.
- b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition D and as specified in 4.5.2 herein and as shown on figure 3 (note 3), or equivalent.
 - (2) $T_A = +125^\circ\text{C}$ minimum.
 - (3) Test duration, 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.4 Group D inspection. Group D inspection shall be in accordance with table IV of method 5005 of MIL-STD-883. End-point electrical parameters shall be as specified in table II herein.

4.4.5 Group E inspection. Group E inspection is required only for device types intended to be marked as radiation hardened (see 3.6.1). When group E testing is performed it shall be in accordance with table V of method 5005 of MIL-STD-883 and 4.5.4 herein.

4.5 Methods of inspection. Methods of inspection shall be specified as follows:

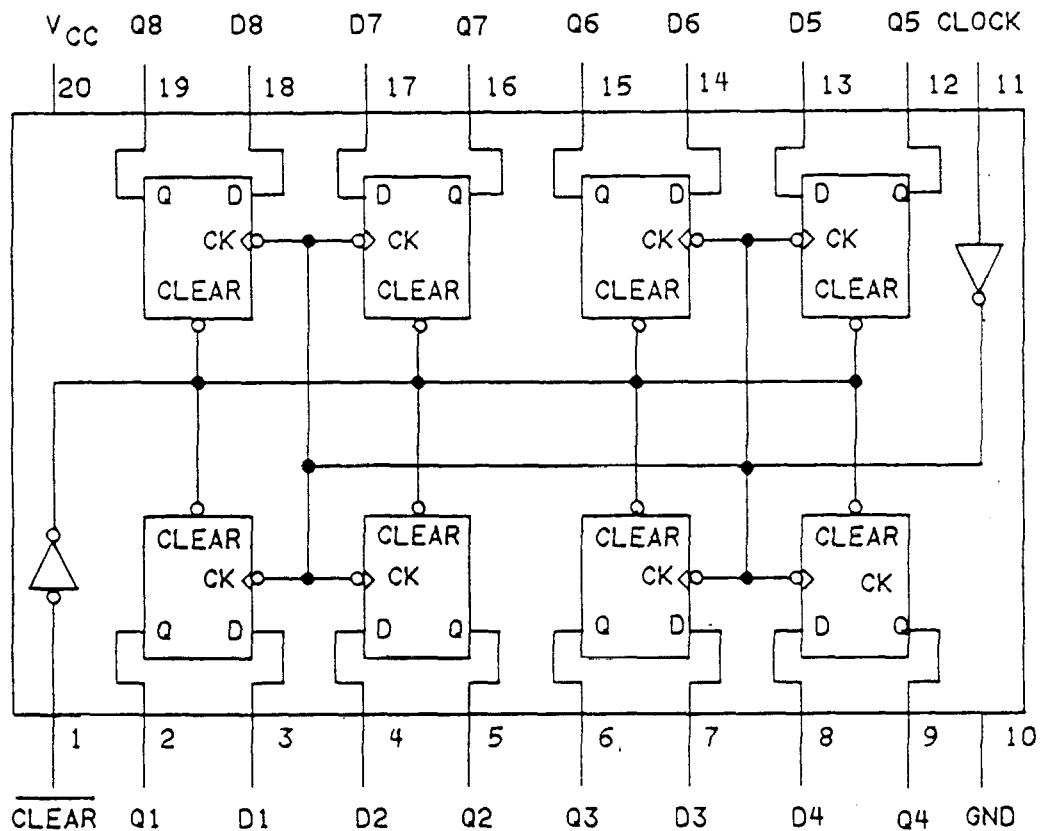
4.5.1 Voltage and current. Unless otherwise specified, all voltages given are referenced to the microcircuit GND terminal. Currents given are conventional current and positive when flowing into the referenced terminal.

Text continues on page 58

Device type 01

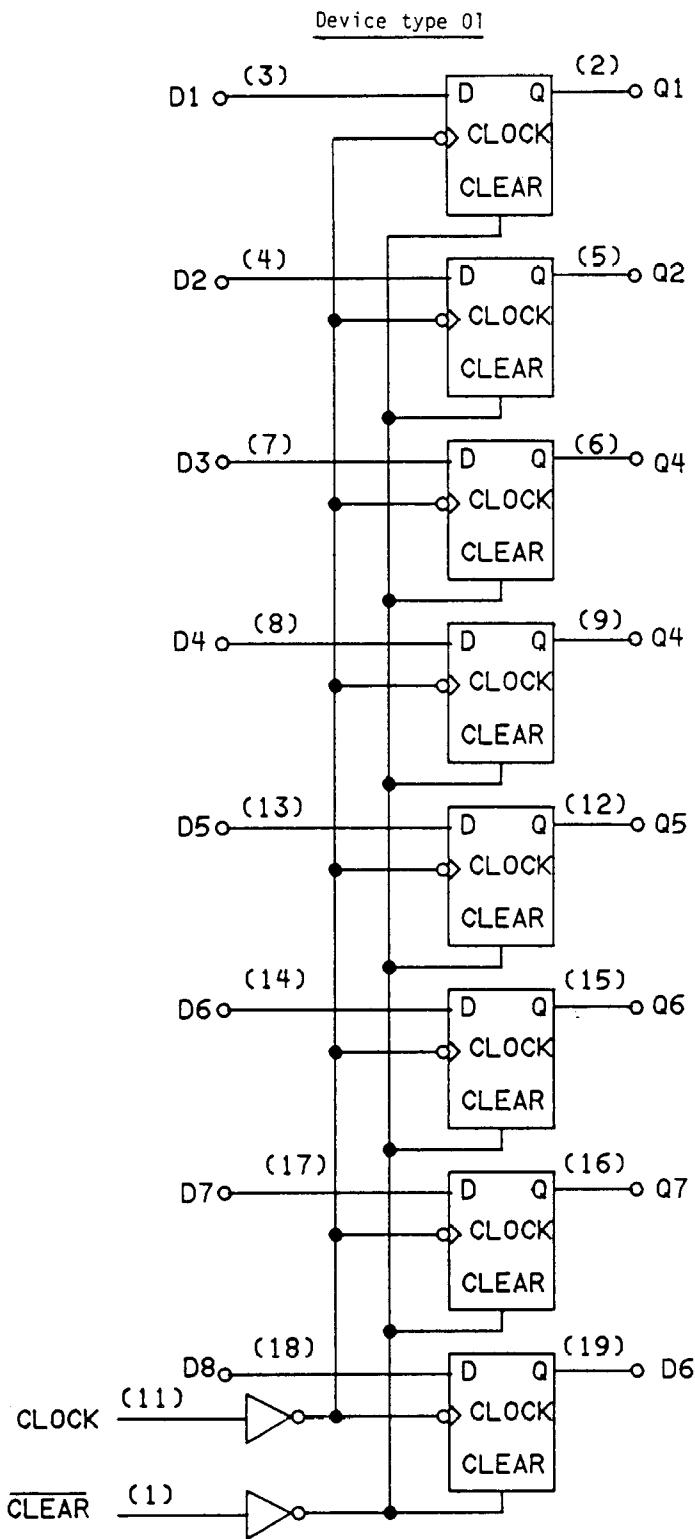
Case R

DUAL-IN-LINE PACKAGE



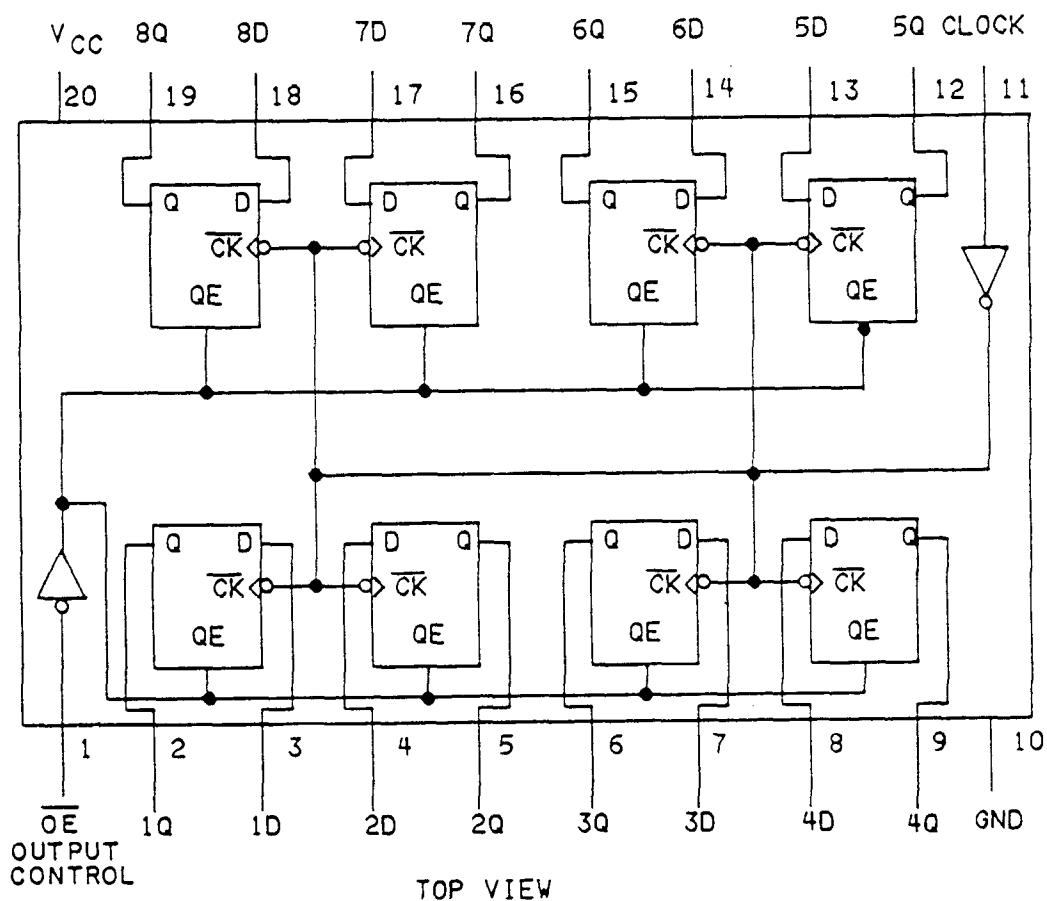
TOP VIEW

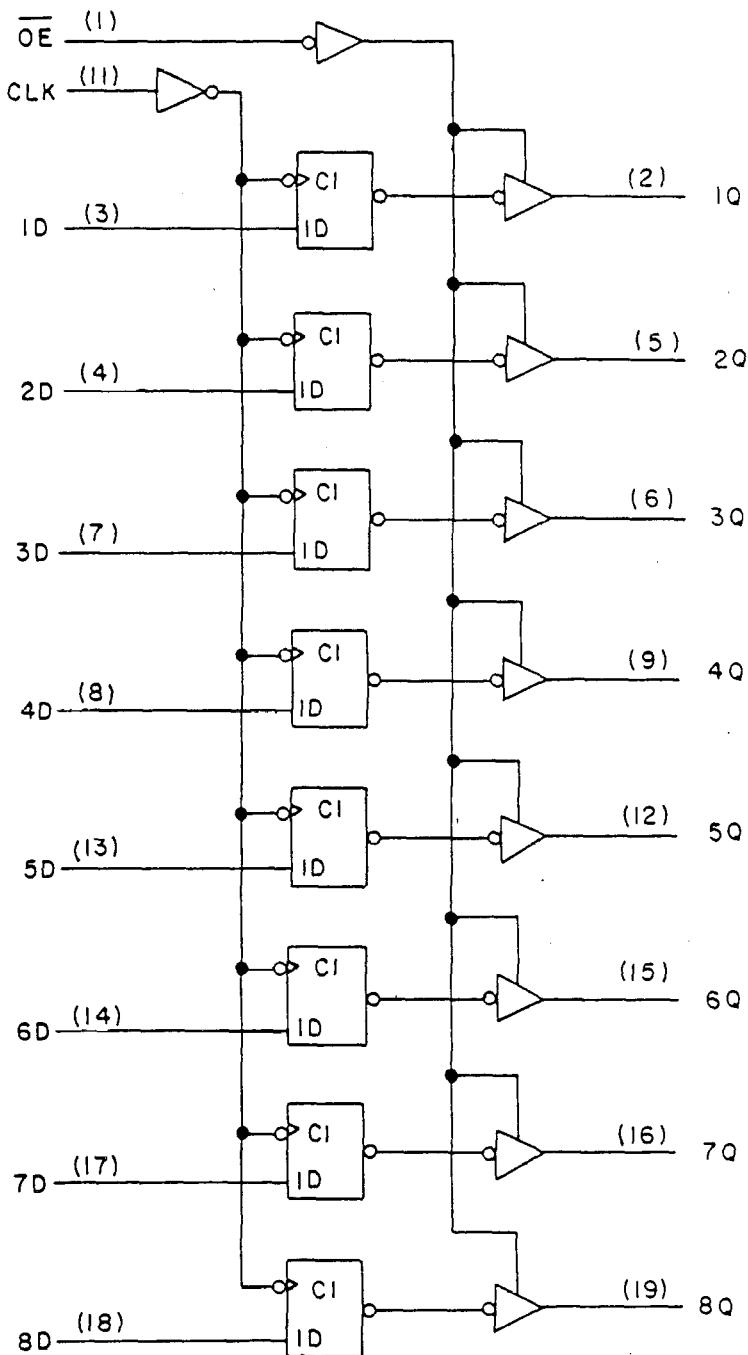
FIGURE 1. Logic diagram and terminal connections (top view).

FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device types 02, 52

DUAL-IN-LINE PACKAGE

FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device types 02, 52

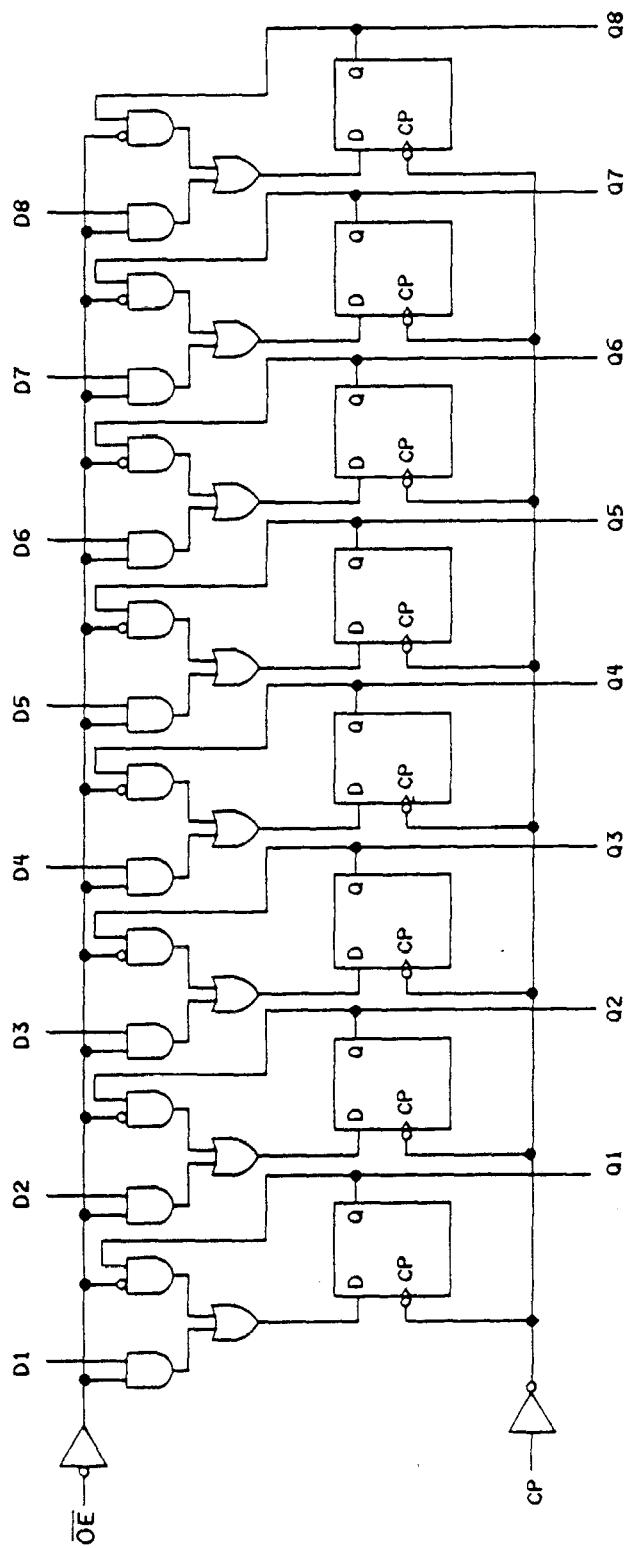
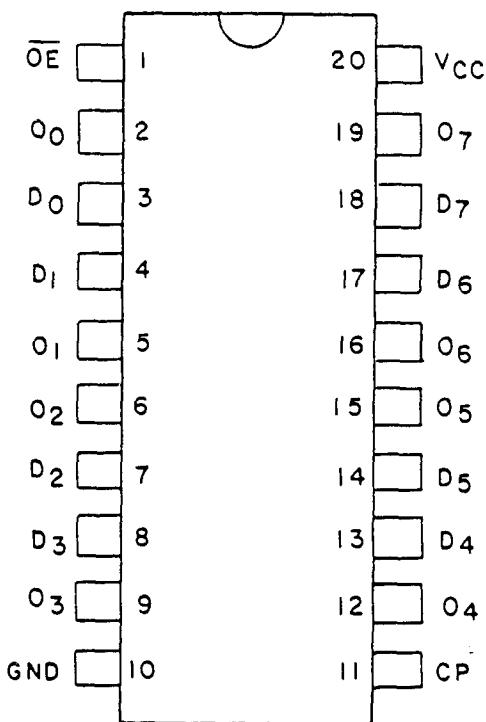
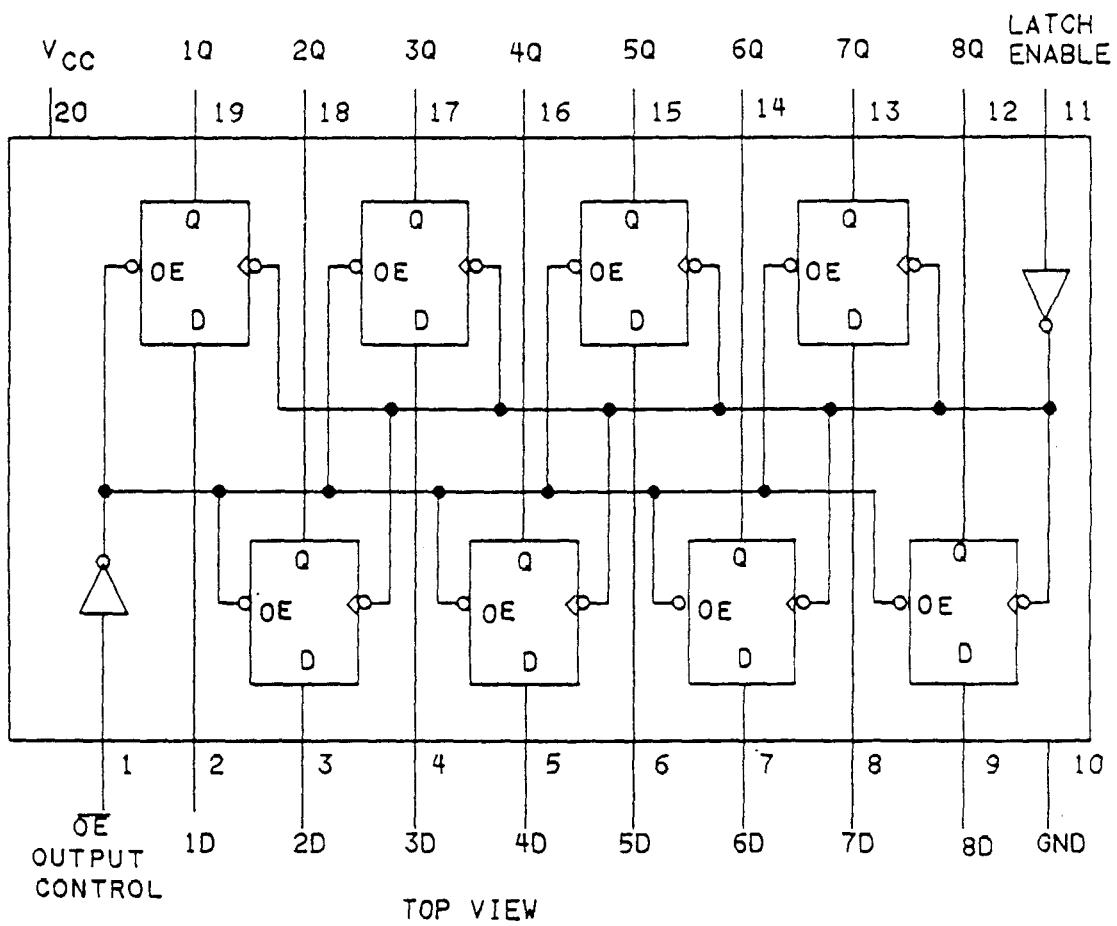
Device type 03

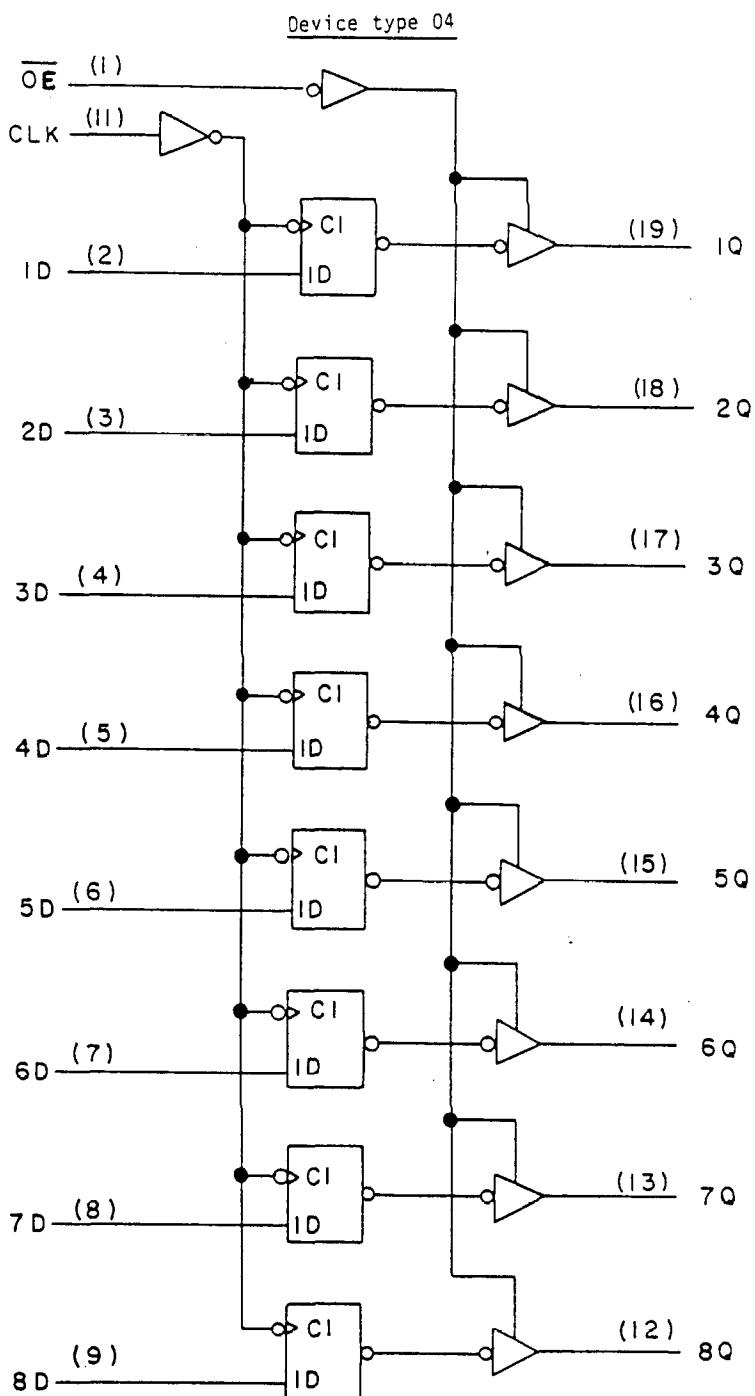
FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device type 03FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device type 04

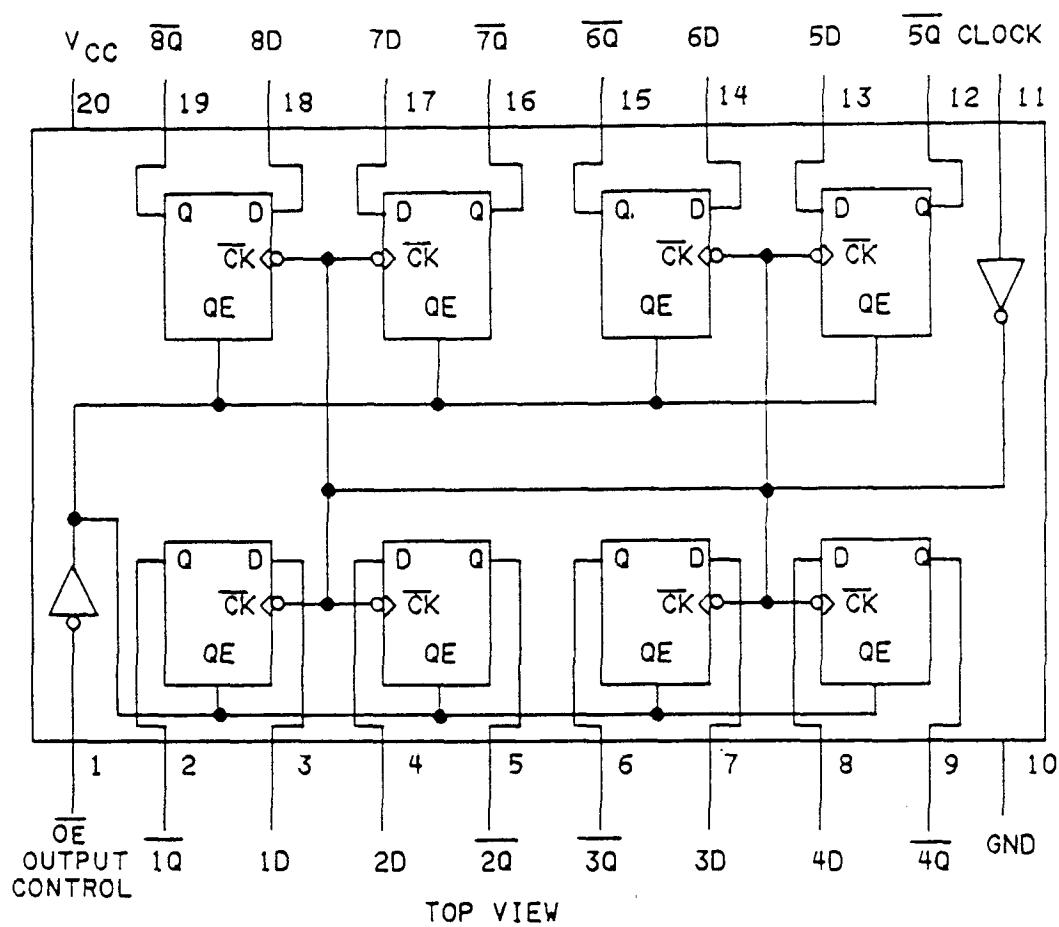
DUAL-IN-LINE PACKAGE

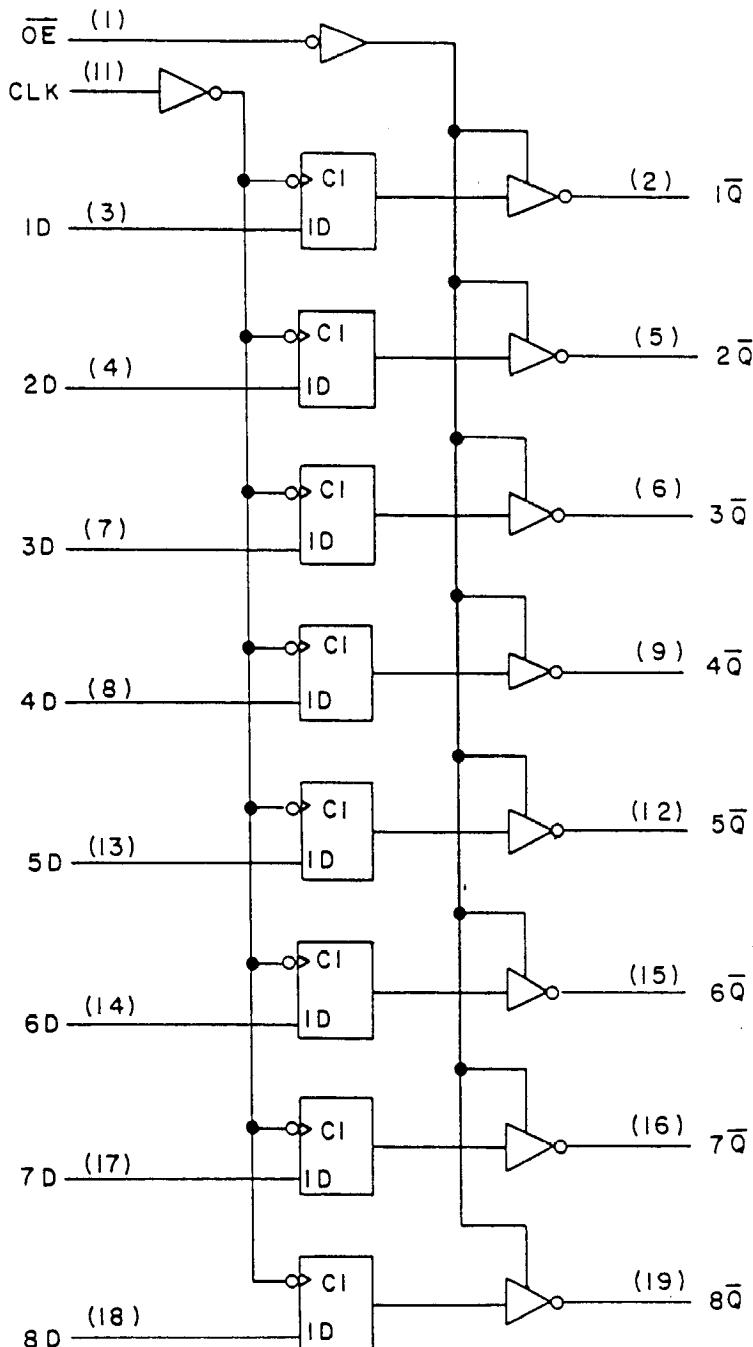
FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device type 05

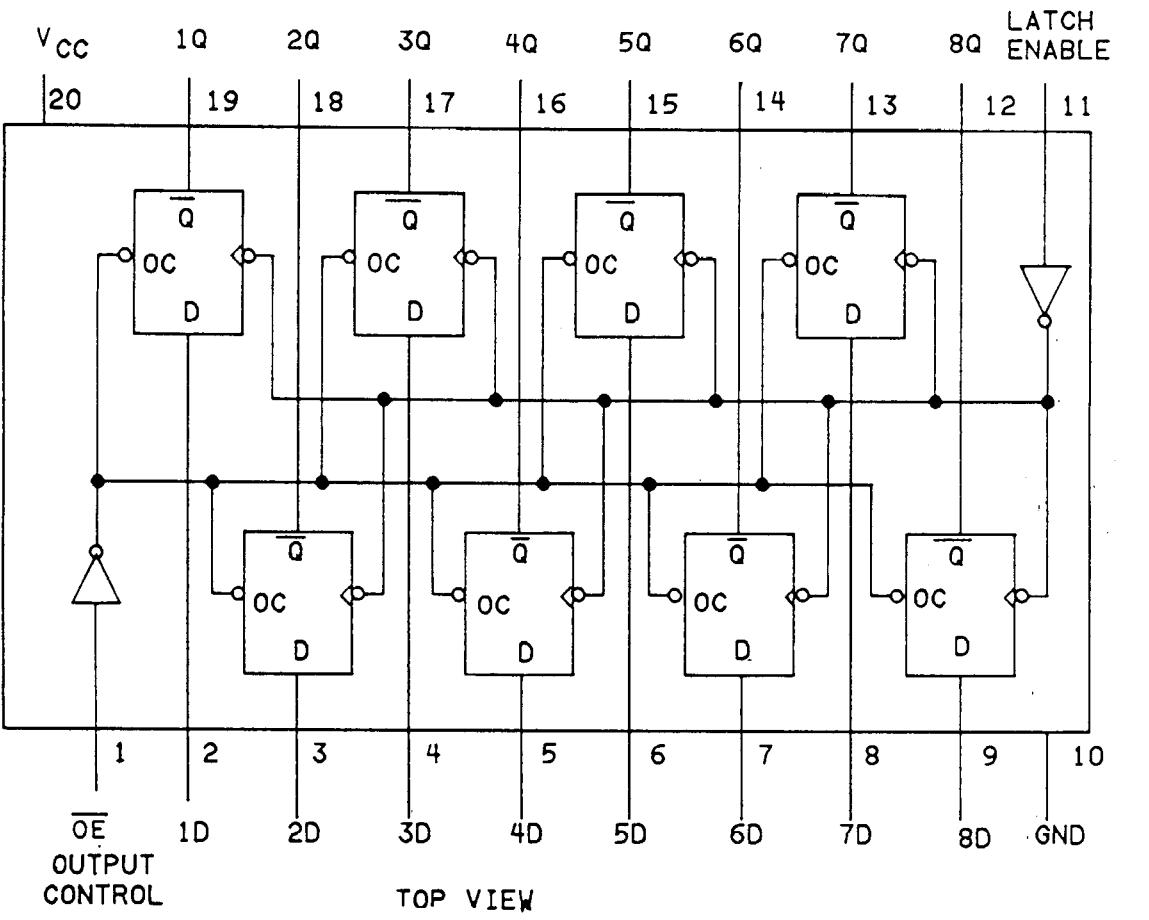
DUAL-IN-LINE PACKAGE

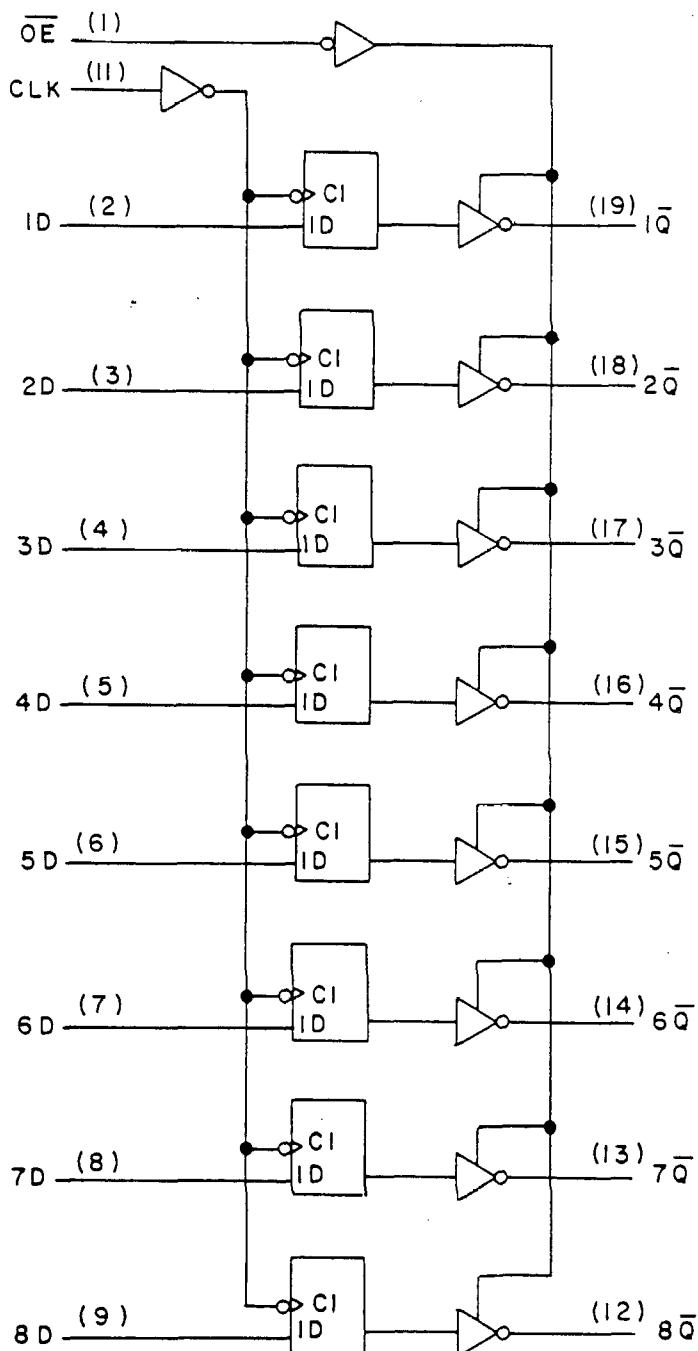
FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device type 05FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device type 06

DUAL-IN-LINE PACKAGE

FIGURE 1. Logic diagram and terminal connections (top view) - Continued,

Device type 06FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device type 01

(Each Flip-Flop)

Inputs			Outputs
Clear	Clock	D	Q
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	Q_0

H = high level (steady state)

L = low level (steady state)

X = don't care

↑ = transition from low to high level

 Q_0 = the level of Q before the indicated steady state input conditions were establishedDevice types 02, 52

Output Control	Clock	Data	Outputs
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

H = high level, L = low level

X = don't care

↑ = transition from low-to-high

Z = high impedance state

 Q_0 = the level of the output before steady state input conditions were establishedDevice type 03

E	Clock	Data	Outputs
H	X	X	Q_0
L	↑	H	H
L	↑	L	L
X	L	X	Q_0

H = high level (steady state)

L = low level (steady state)

X = don't care

↑ = transition from low-to-high

 Q_0 = the level of Q before the indicated steady state input conditions were establishedDevice type 04

Output Control	Clock	Data	Outputs
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

H = high level, L = low level

X = don't care

↑ = transition from low-to-high

Z = high impedance state

 Q_0 = the level of the output before steady state input conditions were establishedDevice type 05

Output Control	Clock	Data	Outputs
L	↑	H	H
L	↑	L	L
L	L	X	\bar{Q}_0
H	X	X	Z

H = high level, L = low level

X = don't care

↑ = transition from low-to-high

Z = high impedance state

 \bar{Q}_0 = the level of the output before steady state input conditions were establishedDevice type 06

Output Control	Clock	Data	Outputs
L	↑	H	H
L	↑	L	L
L	L	X	\bar{Q}_0
H	X	X	Z

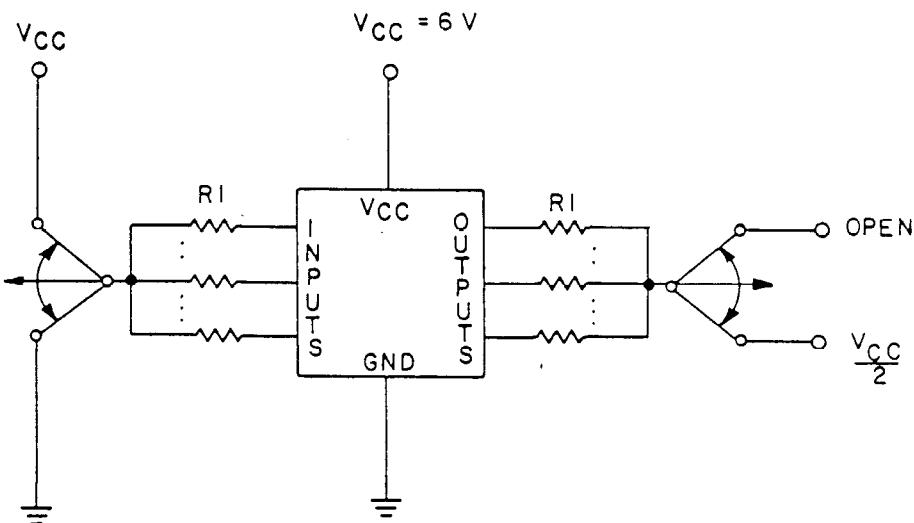
H = high level, L = low level

X = don't care

↑ = transition from low-to-high

Z = high impedance state

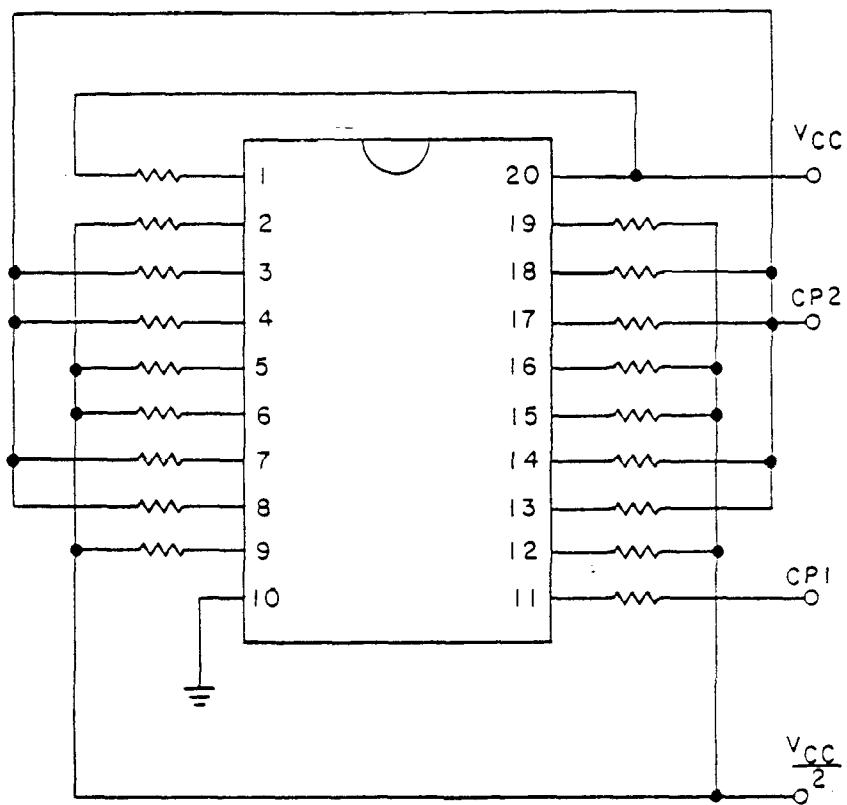
 \bar{Q}_0 = the level of the output before steady state input conditions were establishedFIGURE 2. Truth tables.



- For static burn-in I, all inputs shall be connected to GND . Outputs may be open or connected to $V_{CC}/2$. Resistors R_1 are optional on both inputs and open outputs, required on outputs connected to $V_{CC}/2$. $R_1 = 600\Omega$ to $47 \text{ k}\Omega$.
- For static burn-in II, all inputs shall be connected through the R_1 resistors to V_{CC} . Outputs may be open or connected to $V_{CC}/2$. Resistors are optional on open outputs, required on outputs connected to $V_{CC}/2$. $R_1 = 680\Omega$ to $47 \text{ k}\Omega$.
- $V_{CC} = 6.0 \text{ V } \pm 0.5 \text{ V}$.

$$\frac{V_{CC}}{2} = \frac{V_{CC}}{2} \pm 0.5 \text{ V.}$$

FIGURE 3. Static burn-test circuits.

Device types 01 and 03FIGURE 3. Dynamic burn-in and life test circuits - Continued.

Device types 02, 05, 52

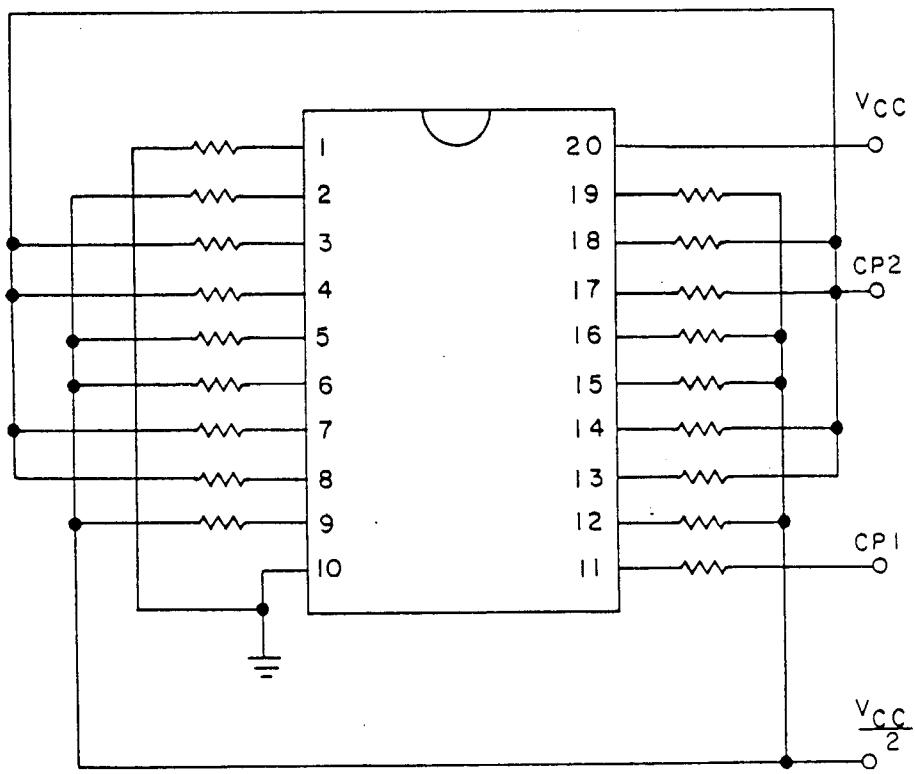
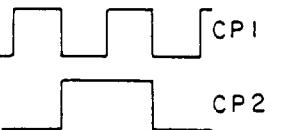
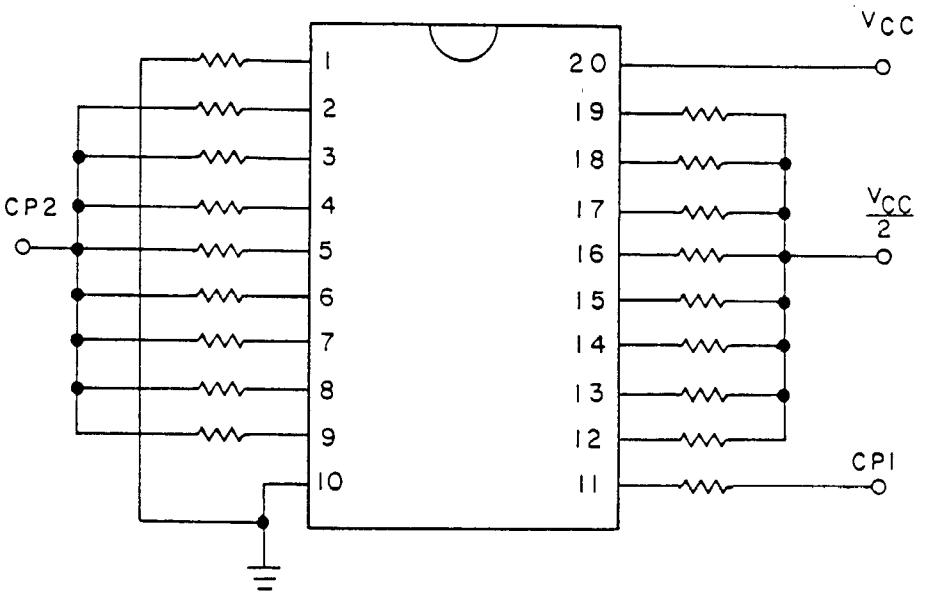
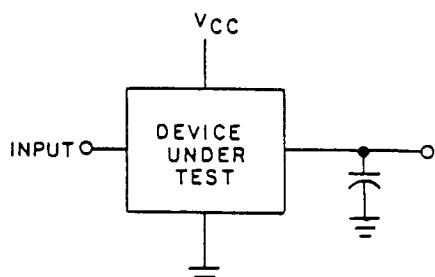


FIGURE 3. Dynamic burn-in and life test circuits - Continued.

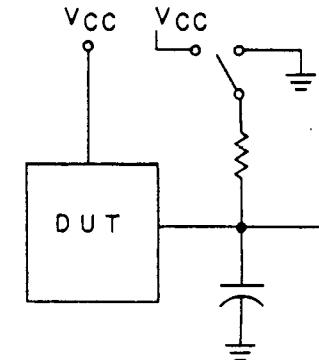
Device types 04 and 06

1. Input resistors = 1 k Ω to 47 k Ω $\pm 20\%$.
2. Output resistors = 1 k Ω $\pm 5\%$ (680 Ω 5% on 02, 04-06, 52).
3. V_{CC} = 6.0 V ± 0.5 V.
4. $\overline{V_{CC}} = \overline{V_{CC}} \pm 0.5$ V.
5. CP1 = 100 kHz, CP2 = 50 kHz $\pm 50\%$ square wave; duty cycle = 50 $\pm 15\%$, V_{IH} = 4.5 minimum to V_{CC} volts maximum; V_{IL} = 0 V $\pm .5$ V; t_{THL}, t_{TLH}, < 500 ns.

FIGURE 3. Dynamic burn-in and life test circuits - Continued.

Device types 01, 03

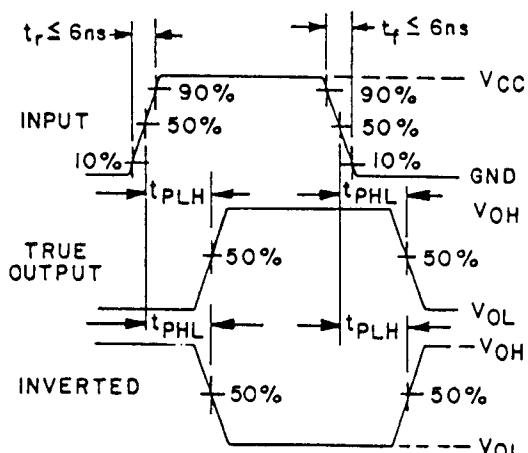
Test circuit for push pull outputs

Device types 02, 04, 05, 06, 52

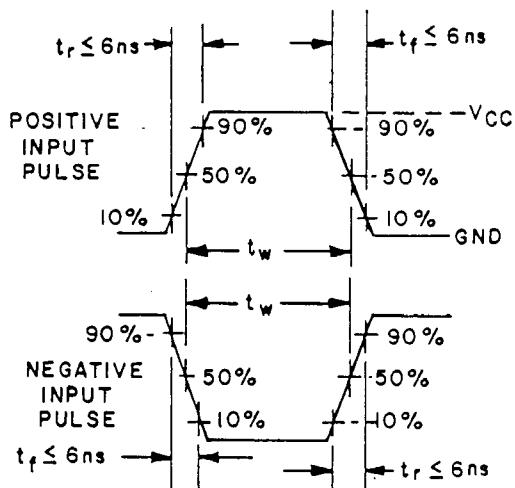
Test circuit for THREE-STATE Test (Notes 1 and 2)

Note 1: C_L includes load and test jig capacitance.
See data sheets for values.

Note 2: $S_1 = V_{CC}$ for t_{pzL} , and t_{pLz} measurements.
 $S_1 = GND$ for t_{pZH} , and t_{pHZ} measurements.

Device types 01, 02, 03, 04, 05, 06, 52

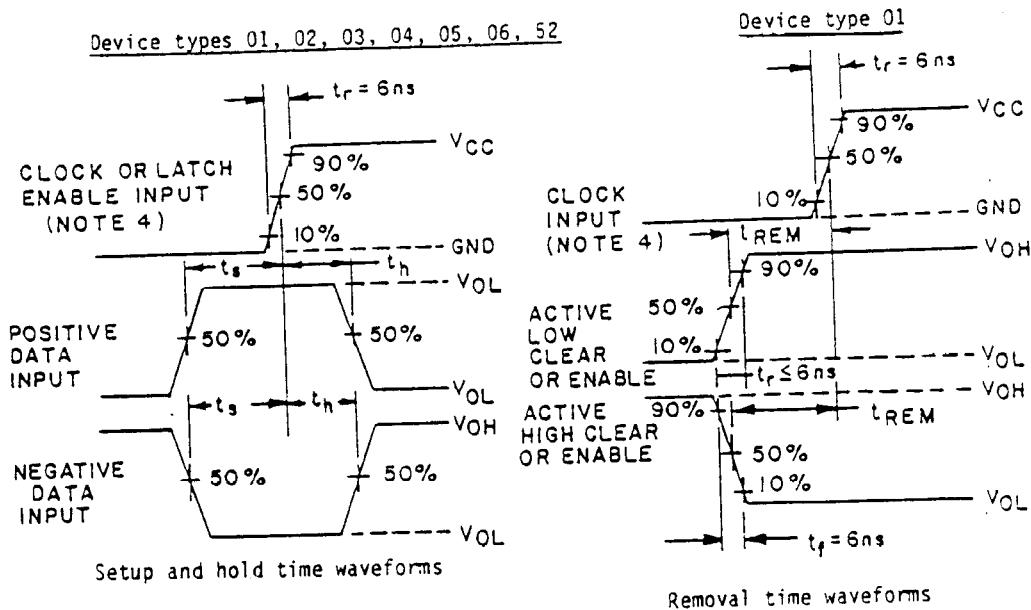
Propagation delay waveforms

Device types 01, 02, 03, 04, 05, 06, 52

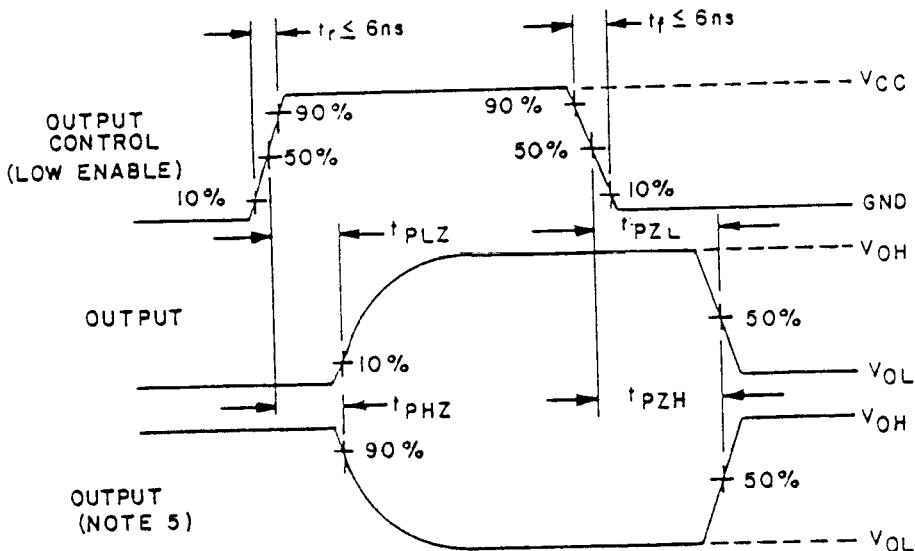
Clock input pulse width waveforms

Minimum pulse width = 16 ns
(01 = 18 ns) (03, 53 = 18 ns)

FIGURE 4. Switching time test circuit and waveforms.



$t_{su} = 20 \text{ ns}$
 $t_{hold} = 5 \text{ ns } (01, 03, 04, 06)$
 $t_{hold} = 10 \text{ ns } (02, 05, 52)$

Device types 02, 04, 05, 06, 52

Note 4: Waveform for negative edge sensitive circuits will be inverted, t_{REM} (20 ns).

Note 5: This waveform is applicable to both THREE-STATE and open drain switching time measurements.

FIGURE 4. Switching time test circuit and waveforms - continued.

TABLE III. Group A Inspection for device type 01.

Symbol	Cases STD-883 method	Test No.	Test no.	terminal conditions 1/												Test limits											
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Measured terminal	Subgroup 1 $T_C = +25^\circ C$	Subgroup 2 $T_C = +125^\circ C$	Subgroup 3 $T_C = -55^\circ C$
V_{IC} (pos)	1	2	1	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0.0	0.0	0.0
V_{IC} (neg)	3	4	5	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	0.0	0.0	0.0	0.0
I_{CCH}	11	12	13	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	0.0	0.0	0.0	0.0
I_{CCL}	14	15	16	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	0.0	0.0	0.0	0.0
V_{OD3}	17	18	19	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	0.0	0.0	0.0	0.0
V_{OD5}	20	21	22	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	0.0	0.0	0.0	0.0
V_{OD6}	23	24	25	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	0.0	0.0	0.0	0.0	
V_{OD7}	26	27	28	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	0.0	0.0	0.0	0.0	
V_{OD8}	29	30	31	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	-14.2 V	-4.2 V	-20 μ A	0.0	0.0	0.0	0.0	
V_{OD9}	32	33	34	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	0.0	0.0	0.0	0.0	
V_{OD10}	35	36	37	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	-14.2 V	-4.2 V	-5.2 mA	0.0	0.0	0.0	0.0	
V_{OD11}	38	39	40	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	0.0	0.0	0.0	0.0	
V_{OD12}	41	42	43	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	0.0	0.0	0.0	0.0	
V_{OD13}	44	45	46	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	-1.2 V	1.2 V	-20 μ A	0.0	0.0	0.0	0.0	
V_{OD14}	47	48	49	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	0.0	0.0	0.0	0.0	
V_{OD15}	50	51	52	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	-1.2 V	1.2 V	-5.2 mA	0.0	0.0	0.0	0.0	

See footnotes at end of table.

TABLE III. Group A Inspection for device type 01 - Continued.

Symbol	MIL-STD-883 Cases & Test no.	Terminal conditions 1/												Test limits								Measured terminal	Subgroup 1/	Subgroup 2/	Subgroup 3/	Unit	
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20						
		CLK	Q1	Q1	B2	Q2	Q3	Q3	Q4	Q4	GND	CLK	Q5	Q5	Q6	Q6	Q7	Q7	Q8	Q8	Y _{CC}	Min	Max	Min	Max		
I _{1H}	3010	63	6 V	GND	GND	GND	6 V	GND	GND	GND	GND	GND	GND	GND	6 V	0.1	0.1	0.1	0.1								
	64	65	66	67	68	69	70	71	72	73	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	D1	D2	D3	D4	D5		
											6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	D6	D7	D8	D9	D10	
I _{1L}	3009	73	GND	6 V	GND	6 V	GND	6 V	GND	6 V	0.1	0.1	0.1	0.1	0.1												
	74	75	76	77	78	79	80	81	82	83	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	0.1	0.1	0.1	0.1	0.1		
											6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	D11	D12	D13	D14	D15	
												6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	D16	D17	D18	D19	D20	
I _{CC}	3012	83	4/								GND																
I ₁		84																									
I _{CC}		86																									
I ₁		87																									
I _{CC}		88																									
I ₁																											
Truth Table Tests 5/ 6/	3014	93	B	L	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	4.5 V	A11 outputs 7/ 8/					
	94	95	96	97	98	99	100	101	102	103	104	105	106	B	B	B	B	B	B	B	B	B	B	B	B	B	B

TABLE III. Group A inspection for device type 01 - Continued.

Symbol	MIL-STD-883 method	Cases No.	Terminal conditions 1/												Test limits			
			Subgroup 10 $T_C = +25^\circ C$				Subgroup 11 $T_C = +125^\circ C$				Subgroup 11 $T_C = -55^\circ C$				Measured terminal	Min	Max	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
t_{PH1}	3003 (Fig. 4)	108	4.5 V	OUT	IN	IN	OUT	OUT	IN	IN	OUT	OUT	IN	IN	OUT	IN	IN	OUT
		109	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		110	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		111	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		112	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		113	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		114	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
t_{PLH1}		115	IN	OUT	4.5 V	4.5 V	OUT	4.5 V	4.5 V	OUT	4.5 V	4.5 V	OUT	4.5 V	4.5 V	OUT	4.5 V	4.5 V
		116	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		117	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		118	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		119	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		120	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		121	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		122	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
t_{PLH2}		123	4.5 V	OUT	IN	IN	OUT	OUT	IN	IN	OUT	OUT	IN	IN	OUT	IN	IN	OUT
		124	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		125	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		126	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		127	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		128	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		129	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		130	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
t_{PL2}		131	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		132	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		133	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		134	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		135	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		136	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		137	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		138	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
t_{TH}		139	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		140	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		141	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		142	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		143	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		144	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		145	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		146	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
t_{TLH}		147	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		148	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		149	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		150	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		151	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		152	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		153	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		154	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

See footnotes at end of table.

TABLE III. Group A inspection for device type 02.

TABLE III. Group A Inspection for device type 02 - Continued.

Symbol	MIL-STD-883 Cases R.2 method	Test No.	Terminal conditions 1/												Test limits						Subgroup 4/ $T_C = 25^\circ C$		
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
I _{DS4}	3011	55 56 59 60 61 62 63	0/E	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	0G	0H	0I	0J	
I _{1H}	3010	64 65 66 67 68 69 70 71 72 73	GND	GND	4 V	4 V	GND	GND	4 V	4 V	GND	GND	4 V	4 V	GND	GND	4 V	4 V	GND	GND	6 V	0/E	
I _{1L}	3009	74 75 76 77 78 79 80 81 82 83	GND	6 V	6 V	6 V	GND	6 V	6 V	GND	6 V	GND	6 V	6 V	GND	GND	6 V	6 V	GND	GND	6 V	0/E	
I _{10H}	84 85 86 87 88 89 90 91	4.2 V	6.0 V	1.2 V	1.2 V	6.0 V	1.2 V	1.2 V	6.0 V	1.2 V	1.2 V	6.0 V	1.2 V	1.2 V	6.0 V	1.2 V	1.2 V	6.0 V	1.2 V	1.2 V	6.0 V	1.2 V	
I _{10L}	92 93 94 95 96 97 98 99	4.2 V	4.2 V	GND	GND	4.2 V	GND	4.2 V	GND	4.2 V	GND	4.2 V	GND	4.2 V									
I _C	3012	100	4/																				PF
I _{C1}		101 102 103 104																					
I _{C2}	105																						
I _{C3}		106																					

TABLE III. Group A Inspection for device type Q2 - Continued.

Symbol	MIL-STD-883 method	Cases R-2	Terminal conditions 1/												Test limits				unit			
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18		
C_0	3012	110	0 V	2V											6 V	0 V	20				V	
	111		0.1A	0.1	0.2	Q2	Q3	0.3	0.4	Q4	GND	CLK	Q5	0.6	0.6	Q7	0.7	0.8	Q8	V _{CC}		
	112																					
	113																					
	114																					
	115																					
	116																					
	117																					
Latch table tests 2/	1014	119	0	2V																		
	110																					
	120																					
	121																					
	122																					
	123																					
	124																					
I_{MAX}	2/	3003	122	0.6	GND	001	IN	001	OUT	IN	001	IN	001	IN	IN	001	IN	IN	001	IN	001	
		123																				
	124																					
	125																					
	126																					
	127																					
	128																					
	129																					
	130																					
	131																					
	132																					
I_{PUL}	2/	3004	133	0.5 V	1N	001	IN	001	OUT	1N	001	IN	001	OUT	IN	IN	001	IN	001	IN	001	
		134																				
	135																					
	136																					
	137																					
	138																					
	139																					
	140																					
I_{PUL2}	2/	3004	134	0.5 V	1N	001	IN	001	OUT	1N	001	IN	001	OUT	1N	001	IN	001	IN	001	IN	
		135																				
	136																					
	137																					
	138																					
	139																					
	140																					
I_{PUL2}	2/	3004	141	0.5 V	1N	001	IN	001	OUT	1N	001	IN	001	OUT	1N	001	IN	001	IN	001	IN	
		142																				
	143																					
	144																					
	145																					
	146																					
	147																					
	148																					
I_{PUL3}	2/	3004	149	0.5 V	1N	001	IN	001	OUT	1N	001	IN	001	OUT	1N	001	IN	001	IN	001	IN	
		150																				
	151																					
	152																					
	153																					
	154																					
	155																					
	156																					

See footnotes at end of table.

TABLE III. Group A Inspection for device type 02 - Continued.

Symbol	MIL-STD-883 method	Cases R,2	Terminal conditions 1/												Test limits															
			Subgroup 10 $T_c = +25^\circ C$						Subgroup 10 $T_c = +125^\circ C$						Subgroup 11 $T_c = -55^\circ C$															
			Test no.	0/E	01	02	Q2	Q3	03	04	Q4	GND	CLK	Q5	05	06	Q6	Q7	D7	D8	Q8	VCC	Mn	Mx						
t_{PDL}	3003 (Fig. 4)	157 158 159 160 161 162 163 164	IN	OUT	GND	OUT	OUT	GND	GND	OUT	GND	GND	GND	OUT	OUT	OUT	OUT	GND	GND	OUT	OUT	4.5 V	26	35						
t_{PHZ}		165 166 167 168 169 170 171 172	OUT	4.5 V	4.5 V	OUT	OUT	4.5 V	OUT	OUT	OUT	OUT	OUT	OUT	4.5 V	4.5 V	OUT	OUT	OUT	OUT	OUT	10/E to 01	10/E to 02	10/E to 03	10/E to 04	10/E to 05	10/E to 06	10/E to 07	10/E to 08	
t_{PLZ}		173 174 175 176 177 178 179 180	OUT	GND	GND	OUT	OUT	GND	OUT	OUT	OUT	OUT	OUT	OUT	4.5 V	4.5 V	OUT	OUT	OUT	OUT	OUT	10/E to 01	10/E to 02	10/E to 03	10/E to 04	10/E to 05	10/E to 06	10/E to 07	10/E to 08	
t_{THL}		181 182 183 184 185 186 187 188	OUT	IN	4.5 V	4.5 V	OUT	4.5 V	4.5 V	OUT	4.5 V	4.5 V	4.5 V	14	4.5 V	4.5 V	4.5 V	4.5 V	12	16	12	16	12	16	12	16				
t_{TLH}		189 190 191 192 193 194 195 196	OUT	IN	GND	IN	OUT	GND	GND	OUT	GND	GND	GND	OUT	IN	4.5 V	4.5 V	OUT	OUT	OUT	OUT	OUT	12	16	12	16	12	16	12	16

See footnotes at end of table.

TABLE III. Group A Inspection for device type Q1.

Symbol	MIL-STD-883 method	Cases A,2	Test no.	E	Test limits															
					Subgroup 1				Subgroup 2				Subgroup 3				Unit			
					TC = +25°C		TC = +125°C		TC = -55°C		TC = -55°C		Min		Max		Min		Max	
V _{IC} (pos)	1	1	1	1	-1 mA	-1 mA	0.4	GND	CLK	0.5	0.6	0.6	0.6	0.7	D7	D8	0.8	V _{CC}	2.7	1.5
V _{IC} (neg)	12	13	14	15	-1 mA	-1 mA	0.4	GND	CLK	0.5	0.6	0.6	0.6	0.7	GND	D1	D2	D3	D4	D5
V _{CC}	21	22	23	24	-1 mA	-1 mA	0.4	GND	CLK	0.5	0.6	0.6	0.6	0.7	E	D1	D2	D3	D4	D5
V _{OH3}	24	25	26	27	-20 μA	-20 μA	20 μA	GND	GND	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	D1	D2	D3	D4	D5
V _{OL3}	26	27	28	29	4.2 V	4.2 V	4.2 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5
V _{OH3}	30	31	32	33	6 V	6 V	6 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5
V _{OL3}	31	32	33	34	6 V	6 V	6 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5
V _{OH3}	34	35	36	37	1.2 V	1.2 V	1.2 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5
V _{OL3}	35	36	37	38	1.2 V	1.2 V	1.2 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5
V _{OH3}	39	40	41	42	1.2 V	1.2 V	1.2 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5
V _{OL3}	40	41	42	43	1.2 V	1.2 V	1.2 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5
V _{OL5}	43	44	45	46	1.2 V	1.2 V	1.2 V	GND	GND	-20 μA	-20 μA	-20 μA	-20 μA	-20 μA	GND	D1	D2	D3	D4	D5

See footnotes at end of table.

TABLE III. Group A inspection for device type 03 - Continued.

TABLE III. Group A inspection for device type 03 - Continued.

See footnotes at end of table.

TABLE III. Group A Inspection for device type 04.

Symbol	MIL-STD-683 method	Cases R,2	Terminal conditions 1/												Test limits								
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
V_{IC} (pos)	1	2	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	V
V_{IC} (neg)	11	12	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA
I_{CC}	21	22	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND
I_{CCZ}	23	6	V	GND	GND	GND	GND	GND	GND	GND	GND	GND											
V_{DH3}	24	25	1.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V
V_{DH5}	32	33	—	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V											
V_{OL3}	40	41	—	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V											
V_{OL5}	48	49	—	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V											

See footnotes at end of table.

TABLE III. Group A Inspection for device type 04 - Continued.

Symbol	MIL-STD-883 Cases Method	Test no.	Terminal conditions V_T												Test limits																	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Measured terminal $I_C = +25^\circ C$	Subgroup 1 $I_C = +25^\circ C$	Subgroup 2 $I_C = +25^\circ C$	Subgroup 3 $I_C = +25^\circ C$	Min	Max	Min	Max	Min	Max
I_{D4}	3011	50	GND	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	0.1	0.1	0.1	0.1	-1.15	1.15	-1.15	1.15		
		58	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		59	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		60	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		61	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		62	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		63	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
I_{1H}	3010	64	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	0.1	0.1	0.1	0.1	-1.15	1.15	-1.15	1.15	
		65	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		66	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		67	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		68	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		69	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		70	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		71	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		72	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		73	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
I_{1L}	3009	74	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	GND	6 V	0.1	0.1	0.1	0.1	-1.15	1.15	-1.15	1.15	
		75	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		76	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		77	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		78	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		79	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		80	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		81	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		82	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		83	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
I_{DHN}	92	84	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V			
		85	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		86	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		87	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		88	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		89	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		90	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		91	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
I_{UL}	92	93	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V	4.2 V			
		94	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		95	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		96	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		97	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		98	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		99	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
I_C	1012	101	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V	4 V
		102	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		103	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		104	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		105	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		106	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		107	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		108	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		109	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		

See footnotes at end of table.

TABLE III. Group A Inspection for device type 04 - Continued.

Symbol	MIL-S-883 Cases method	Cases no.	Terminal conditions 1/																		Test limits								
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Measured terminal	Subgroup 4 $T_C = +25^\circ C$	Subgroup 5 $T_C = +125^\circ C$	Subgroup 6 $T_C = +55^\circ C$			
I_0	3012	110	6 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
Truth table tests 2/ 6)	3014	118	8	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	6 V	Q1	V _{CC}	pF			
		119	-	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	-	-	-	-			
		120	-	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	-	-	-	-			
		121	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		122	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		123	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		124	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		125	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
I_{MAX}	9/	3003	125	GND	IN	IN	IN	IN	IN	IN																			
		126	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		127	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		128	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		129	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		130	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		131	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
		132	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
t_{PHL2}	(Fig. 4)	2003	132	-	IN	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V																	
		133	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		134	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		135	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		136	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		137	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		138	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		139	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		140	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
t_{PHL2}		141	-	IN	GND	GND	GND	GND	GND	GND	GND																		
		142	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		143	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		144	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		145	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		146	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		147	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
		148	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
t_{PHL2}		149	-	IN	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V																	
		150	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		151	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		152	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		153	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		154	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		155	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		156	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
t_{PHL2}		157	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		158	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		159	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		160	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		161	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		162	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		163	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		164	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

TABLE III. Group A inspection for device type 04 - Continued.

See footnotes at end of article.

TABLE III. Group A inspection for device type 05.

TABLE III. Group A Inspection for device type 05 - Continued.

Symbol	MTL-Spec No. 2	Class No. 3	Terminal conditions 3/												Test limits						
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
I _{Q1}	0/6	Q1	D1	0/2	Q2	Q3	0/3	D4	0/4	GND	CLK	UP	0/5	0/6	0/6	Q7	0/7	0/8	Q8	V _{CC}	Measured terminal
I _{Q4}	30/11	56	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	LAND	Subgroup 2/ IC = 25°C
I _{Q5}	58	59	60	61	62	63	Subgroup 3/ IC = 55°C
I _{LH}	20/10	64	65	66	67	68	69	70	71	72	73	Subgroup 4/ IC = 25°C
I _{LL}	30/09	74	75	76	77	78	79	80	81	82	83	Subgroup 4/ IC = 55°C
I _{ULH}	4/4	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80	81	82	83	Subgroup 4/ IC = 25°C
I _{ULC}	2/2	93	94	95	96	97	98	99	Subgroup 4/ IC = 55°C
I _{UC}	30/12	100	101	102	103	104	105	106	107	108	109	109	109	109	109	109	109	109	109	109	Subgroup 4/ IC = 55°C

TABLE III. Group A inspection for device type 05 - Continued.

Symbol	MIL-STD-883 method	Cases 0,2	Terminal conditions 1/																			Test limits							
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Measured terminal	Subgroup 4 $T_c = +25^\circ\text{C}$			Subgroup 4 $T_c = +25^\circ\text{C}$		
t_0	3012	110	6 V	$\underline{2}/$																			6 V	0	20	0	20	0	PF
Truth table tests 5/	3014	118	0	H	B	A	L	GND	Q4	GND	CLK	Q5	D5	D6	V _{DS}	V _{GS}													
		119																											
		120																											
		121																											
		122																											
		123																											
		124																											
		125																											
		126																											
		127																											
		128																											
		129																											
		130																											
t_{MAX} 9/	3003	131	GND	OUT	IN	IN	OUT	OUT	IN	IN	OUT	OUT	IN	IN	OUT	OUT	IN	IN	OUT	IN	IN	OUT		4.5 V	33	25	33	Hz	
		132																											
		133																											
		134																											
		135																											
		136																											
		137																											
		138																											
t_{PHL2}	3003 (Fig. 4)	139	OUT	IN	GND	OUT	GND	GND	IN	OUT	IN	OUT	OUT	IN	OUT	GND	IN	OUT	IN	OUT	IN	OUT		CLK to Q1	32	42	32	ns	
		140																											
		141																											
		142																											
		143																											
		144																											
		145																											
		146																											
t_{PLH2}		147	OUT	IN	4.5 V	OUT	4.5 V	4.5 V	IN	OUT	4.5 V	4.5 V	OUT	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V		CLK to Q2					
		148																											
		149																											
		150																											
		151																											
		152																											
		153																											
		154																											
t_{PZH}		155	IN	OUT	GND	OUT	GND	OUT	IN	OUT	GND	OUT	IN	OUT	IN	OUT	GND	OUT	IN	OUT	GND	OUT		OUT Q1	31	41	31		
		156																											
		157																											
		158																											
		159																											
		160																											
		161																											
		162																											

TABLE III. Group A inspection for device type 05 - Continued.

See footnotes at end of table.

TABLE III. Group A Inspection for device type 06.

Symbol	Cases MIL-3883 method	Test no.	Terminal conditions 1/												Test limits						Measured terminal Subgroup 1 $T_C = -25^\circ C$	Subgroup 2 $T_C = +125^\circ C$	Subgroup 3 $T_C = +55^\circ C$	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20		
V_{IC} (pos)	1	1	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0/E	2/-1.5
V_{IC} (neg)	11	12	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0/E	-1.5
I_{OLH}	13	14	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0/E	-1.5
I_{COL}	15	16	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0/E	-1.5
I_{GCZ}	17	18	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0/E	-1.5
V_{OH3}	19	20	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0/E	-1.5
V_{OL3}	21	22	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	6 V	V _{CC}	0.2
I_{OLH}	23	24	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V
I_{COL}	25	26	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V
I_{GCZ}	27	28	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V
V_{OH3}	29	30	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V
V_{OL3}	31	32	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OH5}	33	34	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	35	36	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	37	38	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	39	40	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	41	42	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	43	44	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	45	46	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	47	48	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	49	50	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	51	52	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	53	54	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	1.2 V	-20 μ A	-20 μ A	5.95
V_{OL3}	55																							

TABLE III. Group A Inspection for device type 06 - Continued.

Symbol	MIL-SID 883 method	Terminal conditions V																		Test limits	
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	
U54	3011	56	57	58	59	60	61	62	63	64	65	66	67	68	69	70	71	72	73	74	Measured current
J1H	3010	64	6 V	GND	6 V	6 V	Subgroup 1 $T_C = +25^\circ C$														
J1L	3009	74	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	6 V	Subgroup 2 $T_C = +125^\circ C$
I _{1ZH}		65	1.2 V	Subgroup 3 $T_C = +55^\circ C$																	
I _{1ZL}		66	1.2 V	Subgroup 4 $T_C = +25^\circ C$																	
I _C	3012	100	4 V	GND	4 V	4 V	P														
I _{C1}		102	4 V	GND	4 V	4 V	-														
I _{C2}		104	4 V	GND	4 V	4 V	-														
I _{C3}		105	4 V	GND	4 V	4 V	-														
I _{C4}		106	4 V	GND	4 V	4 V	-														
I _{C5}		107	4 V	GND	4 V	4 V	-														
I _{C6}		108	4 V	GND	4 V	4 V	-														

See footnotes at end of table.

TABLE III. Group A Inspection for device type 06 - Continued.

Symbol	MIL-STD-883 Cases R.2 method	Test no.	Terminal conditions 1/												Measured terminal												Test limits											
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Subgroup 4 $T_C = +25^\circ C$	Subgroup 5 $T_C = +125^\circ C$	Subgroup 6 $T_C = -55^\circ C$	Subgroup 7 $T_C = +25^\circ C$	Subgroup 8 $T_C = +125^\circ C$	Subgroup 9 $T_C = -55^\circ C$	Subgroup 10 $T_C = +25^\circ C$	Subgroup 11 $T_C = -55^\circ C$	Unit							
C_0	3012	110 111 112 113 114 115 116 117	6 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
Truth table 5/6/	3014	118 119 120 121 122 123 124	6 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-			
f_{MAX} 9/	3003	125 126 127 128 129 130 131 132	GND	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN	IN																
t_{PHL2} (Fig. 4)	3003	133 134 135 136 137 138 139 140	-	IN	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND															
t_{PLH2}	141 142 143 144 145 146 147 148	-	IN	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V	4.5 V															
t_{PZH}	149 150 151 152 153 154 155 156	-	IN	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND																

See footnotes at end of table.

TABLE III. Group A Inspection for device type 00 - Continued.

Symbol	MIL-SID-841 method	Case # 8,2	Terminal conditions 1/												Test limits							
			Subgroup 9				Subgroup 10				Subgroup 11				Measured terminal		Subgroup 9		Subgroup 10		Subgroup 11	
			Test no.	0/1	0/2	0/3	0/4	0/5	0/6	0/7	0/8	0/9	0/10	0/11	Min	Max	Min	Max	Min	Max	Min	Max
t _{PZL}	3003 (Fig. 4)	157	IN	4.5 V	4.5 V	14.5 V	14.5 V	1.5 V	1.5 V	4.5 V	4.5 V	4.5 V	4.5 V	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		158	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		159	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		160	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		161	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		162	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		163	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		164	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
														OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
t _{PDZ}		165	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		166	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		167	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		168	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		169	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		170	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		171	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		172	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
														OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
t _{PZL}		173	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		174	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		175	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		176	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		177	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		178	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		179	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		180	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
														OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
t _{PDZ}		181	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		182	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		183	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		184	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		185	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		186	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		187	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		188	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
														OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
t _{PDZ}		189	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		190	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		191	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		192	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		193	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		194	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		195	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
		196	-	-	-	-	-	-	-	-	-	-	-	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT

See footnotes at end of table.

TABLE III. Group A Inspection for device type 52.

Symbol	MIL-STD-883 Case R method	Test no.	Terminal conditions V												Test limits													
			2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Measured terminal	Subgroup 1 TC = -25°C	Subgroup 2 TC = -125°C	Subgroup 3 TC = -55°C	Unit		
V_{IC} (pos)	1, 2, 3, 4, 5, 6, 7, 8, 9, 10	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	1 mA	GND	0/E	0.1	1.5	V		
V_{IC} (neg)	11, 12, 13, 14, 15, 16, 17, 18, 19, 20	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA	GND	0/E	0.1	-1.5	V		
I_{CCH}	3005	21	GND	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	VCC	0.2	8.0	mA			
I_{COL}	22	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	-	-	-	-		
I_{COL}	23	5.5 V	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	-	-	-	-		
V_{OH3}	3006	24, 25, 26, 27, 28, 29, 30, 31	10.8 V	-20 μ A	12.0 V	2.0 V	-20 μ A	12.0 V	2.0 V	-20 μ A	12.0 V	2.0 V	-20 μ A	12.0 V	2.0 V	-20 μ A	12.0 V	2.0 V	-20 μ A	12.0 V	2.0 V	-20 μ A	-	5.90	5.90	5.90		
V_{OH5}	32, 33, 34, 35, 36, 37, 38, 39	-6.0 mA	2.0 V	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	2.0 V	-6.0 mA	-	0.1	5.48	5.2	5.48
V_{OL3}	3007	40, 41, 42, 43, 44, 45, 46, 47	20 μ A	0.8 V	0.8 V	20 μ A	10.8 V	10.8 V	20 μ A	10.8 V	10.8 V	20 μ A	10.8 V	10.8 V	20 μ A	10.8 V	10.8 V	20 μ A	10.8 V	10.8 V	20 μ A	10.8 V	0.8 V	0.8 V	0.8 V	0.8 V		
V_{OL5}	48, 49, 50, 51, 52, 53, 54, 55	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	0.8 V	6.0 mA	10.8 V	

TABLE III. Group A Inspection for device type 52 - Continued.

Symbol	Mil Std No	Class R	Test No.	Terminal conditions 1/																Test limits								
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Measured terminal	Subgroup 1 Tc = -55°C	Subgroup 2 Tc = -45°C	Subgroup 3 Tc = -35°C	Unit
I104	3011	56	57	GND	0.1	0.2	0.3	0.4	0.5	0.6	0.7	0.8	0.9	1.0	1.1	1.2	1.3	1.4	1.5	1.6	1.7	1.8	1.9	2.0	-1.35	-1.35	-1.35	mA
		58	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		59	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		60	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		61	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		62	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		63	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I114	3010	64	65	15.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	0.1	0.05	0.05	mA
		66	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		67	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		68	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		69	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		70	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		71	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		72	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		73	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I115	3009	74	-	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	15.5 V	0.1	-0.05	-0.05	mA	
		75	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		76	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		77	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		78	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		79	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		80	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		81	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		82	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		83	-	15.5 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I102H	3011	84	12.0 V	2.0 V	0.8 V	0.8 V	2.0 V	0.8 V	2.0 V	0.8 V	2.0 V	0.1	0.2	0.2	mA													
		85	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		86	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		87	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		88	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		89	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		90	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		91	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		92	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		93	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		94	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		95	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		96	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		97	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		98	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		99	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I1C	3012	100	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I1C	101	102	-	2V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I1C	103	104	-	2V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I1C	105	106	-	2V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I1C	107	108	-	2V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I1C	109	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

See footnotes at end of table.

TABLE III. Group A inspection for device type 52 - Continued.

Symbol	MIL-STD-883 Case No.	Test method	Terminal conditions 1/												Measured terminal				Test limits			
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
C ₀	301.2	110 111 112 113 114 115 116 117	6 V Z/ Z/ Z/ Z/ Z/ Z/ Z/																			PF
Truth table tests 2/ 5/	301.4	118 119 120 121 122 123 124	B H B B L L H	X A B B A L A	X A B B A L A	X A B B A L A	X A B B A L A	X A B B A L A	GND GND GND GND GND GND GND	GND GND GND GND GND GND GND	GND GND GND GND GND GND GND	GND GND GND GND GND GND GND	GND GND GND GND GND GND GND	GND GND GND GND GND GND GND	6 V 0.02 0.02 0.02 0.02 0.02 0.02	0.02 0.02 0.02 0.02 0.02 0.02 0.02	20					
t _{PHL2}	300.3 (Fig. 4)	125 126 127 128 129 130 131 132	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V	4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V	0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8	21 22 23 24 25 26 27 28	29			MHz	
t _{PHL2}	141 142 143 144 145 146 147 148	0.01 IN GND GND GND GND GND GND GND	OUT IN GND GND GND GND GND GND GND	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	IN OUT IN OUT IN OUT IN OUT	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V	4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V	0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8	32 33 34 35 36 37 38 39	40				
t _{PHL2}	149 150 151 152 153 154 155 156	IN OUT IN OUT IN OUT IN OUT	4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V	OUT OUT OUT OUT OUT OUT OUT OUT	OUT OUT OUT OUT OUT OUT OUT OUT	OUT OUT OUT OUT OUT OUT OUT OUT	OUT OUT OUT OUT OUT OUT OUT OUT	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V	4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V 4.5 V	0.01 0.02 0.03 0.04 0.05 0.06 0.07 0.08	0/E 0/E 0/E 0/E 0/E 0/E 0/E 0/E	0/E 0/E 0/E 0/E 0/E 0/E 0/E 0/E					

See footnotes at end of table.

TABLE III. Group A inspection for device type 52 - Continued.

1/ Output pins not designated may be "high" level logic, or open. Input pins not designated may be high level logic or low level logic. Exceptions are as follows:

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44
The terminal shall be open.

IC (new) tests. The CC test shall be open.

• CCC 1000, 100e Sainte-Catherine, Montréal, Québec H3C 1J4.

21 *For Fundamental Ideas and All True Forms*

תְּהִלָּה וְעַמְּדָה בְּבֵית אֱלֹהִים יְהוָה

... 2.5% (100%)

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41 555 444-130

2/ 1833 RECORDED IN DEWESON S.

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0/ A = 2.4 V; B = 0.4 V.

1/ X = Indeterminate outcome variable.

8 / Output shafts: High > 1.5 V; Low < 1.5 V. 1 hour

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9/ f_{MAX}: maximum limit specified by the frequency of the

the input frequency. The f_{MAX} requirement is const

pulse repetition period set to that given in the list.

4.5.2 Burn-in and life test cool down procedures. When the burn-in and life tests are completed and prior to removal of bias voltages, the devices under test (DUT) shall be cooled to within $+10^{\circ}\text{C}$ of their power stable condition at room temperature; then, electrical parameter end-point measurements shall be performed.

TABLE IV. Delta limits at $+25^{\circ}\text{C}$.

Parameter 1/	Device types	
	All	
I_{CC}		$\pm 30 \text{ nA}$

1/ The above parameters shall be recorded before and after the required burn-in and life tests to determine deltas (Δ).

4.5.3 Quiescent supply current (I_{CC} test). When performing quiescent supply current measurements (I_{CC}), the meter shall be placed so that all currents flow through the meter.

4.5.4 Radiation hardness assurance (RHA) testing. The RHA testing shall be performed in accordance with test procedures and sampling specified in table V of method 5005 of MIL-STD-883 and herein:

- Before irradiation, selected samples shall be assembled in qualified packages and pass the governing electrical parameters (group A, subgroup 1 at $+25^{\circ}\text{C}$) and also be subjected to the threshold-voltage test in table V in order to calculate the delta threshold (ΔV_T) after irradiation.
- The devices shall be subjected to a total radiation dose as specified in MIL-M-38510 for the radiation hardness assurance (RHA) level being tested, and meet the end point electrical parameters as defined in table VI at $+25^{\circ}\text{C}$, after exposure. The start and completion of the end point electrical parameter measurements shall not exceed 2 hours following irradiation.
- Threshold-voltage test circuit conditions shall be as specified in table V and figure 5. In situ and remote testing, the tests shall be performed with the devices biased in accordance with table VII and bias may be interrupted for up to 1 minute to remove devices to the remote bias fixture.
- After irradiation, the devices shall pass the truth table test as specified in subgroup 7 in table III or if subgroup 7 is not required, then an equivalent truth table test shall be performed.

TABLE V. Threshold-voltage test circuit conditions.

Device type	GND	5 V	V _{TN} measured at	GND	-5.0 V	V _{TP} measured at
			-10 μA supply			10 μA supply
01,02,03, 05,52	1	20	3,4,7,8,10,11,13 14,17,18	1	3,4,7,8,10,11,13 14,17,18	20
04,06	1	20	2-11	1	2-11	20

TABLE VI. Radiation hardening end-point electrical parameters at +25°C.

Parameter	All device types	V _{CC}	V _{CC}
		Device types	Device type
		01-06	52
V _{TN}	-0.2 V min	5 V	5 V
V _{TP}	2.8 V max	5 V	5 V
ΔV _T	1.0 V max	5 V	5 V
I _{CC}	100 x max limit	6 V	5.5 V
t _{PLH}	1.35 x max limit	4.5 V	4.5 V
t _{PHL}	1.35 x max limit	4.5 V	4.5 V

TABLE VII. Bias during exposure to radiation.

Device type	Pin connections		
	V _{CC} = 4.5 V dc (through a 30- to 60-kilohm resistor)	GND	V _{CC} = 4.5 V dc
01,02,03,05,52	1, 3, 4, 7; 8, 11, 13, 14, 17, 18	10	20
04,06	1-9, 11	10	20

Pins not designated are open or connected to 4.5 V dc through a 30- to 60-kilohms resistor.

4.6 Data reporting. When specified in the purchase order or contract, a copy of the following data, as applicable, shall be supplied.

- a. Attributes data for all screening tests (see 4.2) and variables data for all static burn-in, dynamic burn-in, and steady-state life tests (see 3.5).
- b. A copy of each radiograph.
- c. The quality conformance inspection data (see 4.4).
- d. Parameter distribution data on parameters evaluated during burn-in (see 3.5).
- e. Final electrical parameters data (see 4.2c).

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this specification are intended for original equipment design application and logistic support of existing equipment.

6.2 Ordering data. The acquisition document should specify the following:

- a. Complete part number (see 1.2).
- b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
- c. Requirements for certificate of compliance, if applicable.

- d. Requirements for notification of change of product or process to the contracting activity in addition to notification to the qualifying activity, if applicable.
- e. Requirements for failure analysis (including required test condition of method 5003 of MIL-STD-883), corrective action and reporting of results, if applicable.
- f. Requirements for product assurance options.
- g. Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements shall not apply to direct purchase by, or direct shipment to the Government.
- h. Requirements for "JAN" marking.
- i. Requirements for total dose radiation testing (see 3.6.1 and 4.5.4), if applicable.

6.3 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-M-38510, MIL-STD-1331, and as follows:

C_i	- - - - -	Input terminal-to-GND capacitance.
GND	- - - - -	Ground zero voltage potential.
I_{CC}	- - - - -	Quiescent supply current.
T_A	- - - - -	Free air temperature.
V_{CC}	- - - - -	Positive supply voltage.

6.4 Logistic support. Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be acquired to device class S for National Aeronautics and Space Administration or class B for Department of Defense (see 1.2.2), lead finish C (see 3.3). Longer length leads and lead forming shall not affect the part number.

6.5 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information shall not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-M-38510.

Military device type	Generic-industry type
01	54HC273
02	54HC374
03	54HC377
04	54HC574
05	54HC534
06	54HC564
52	54HCT374

6.6 Handling. MOS devices must be handled with certain precautions to avoid damage due to accumulation of static charge. Input protective devices have been designed in the chip to minimize the effect of this static build up. However, the following handling practices are recommended:

- a. Devices should be handled on benches with conductive and grounded surface.
- b. Ground test equipment, tools, and operator.
- c. Do not handle devices by the leads.
- d. Store devices in conductive foam or carriers.
- e. Avoid use of plastic, rubber, or silk in MOS areas.
- f. Maintain relative humidity above 50 percent, if practical.

Custodians:

Army - ER
Navy - EC
Air Force - 17
NASA - NA

Preparing activity:

Air Force - 17

Agent:

DLA - ES

Review activities:

Army - AR, MI
Air Force - 11, 19, 85, 99
DLA - ES

(Project 5962-0849)

User activities:

Army - SM
Navy - AS, CG, OC, MC, SH